



Dell PowerEdge Customer Deck

D&H

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DELLTechnologies

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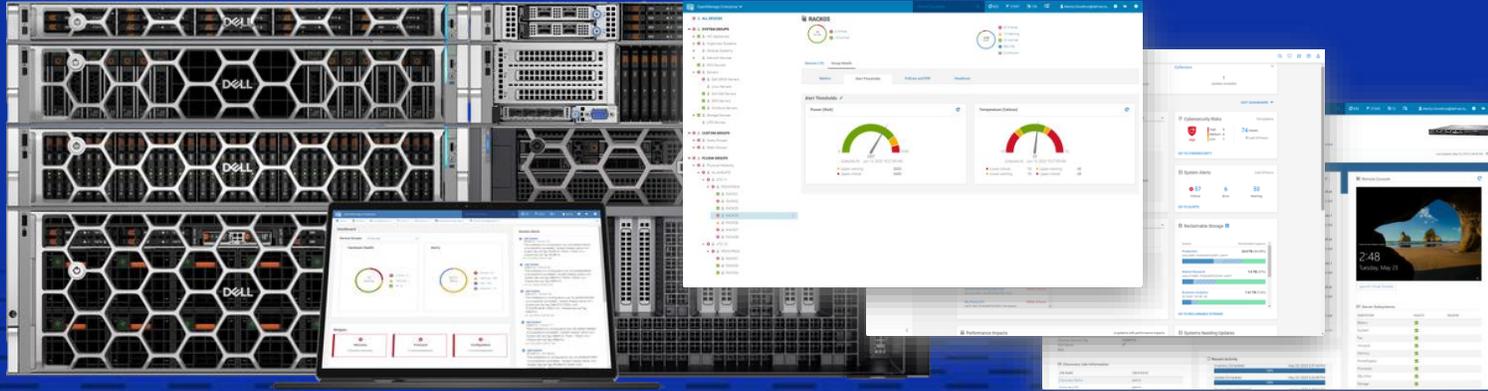
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PowerEdge Servers

Purpose-built | Intelligent | Cyber Resilient



Purpose-built

Scale AI, Edge & Performance Anywhere



Intelligent

Accomplish more with Automation & Improve Operational Efficiencies



Cyber Resilient

Accelerate Zero Trust Adoption

Subscribe or Consume aaS with APEX

Prepare Your Data Center for AI and Transformation



AI-Driven Operations

Automate provisioning and delivery of IT resources for real-time efficiency

Streamlined Automation



AI-Ready Foundations

Invest in scalable, AI-ready infrastructure.

AI-Driven Innovation



Ongoing Improvement

Minimize technical debt with steady, proactive upgrades

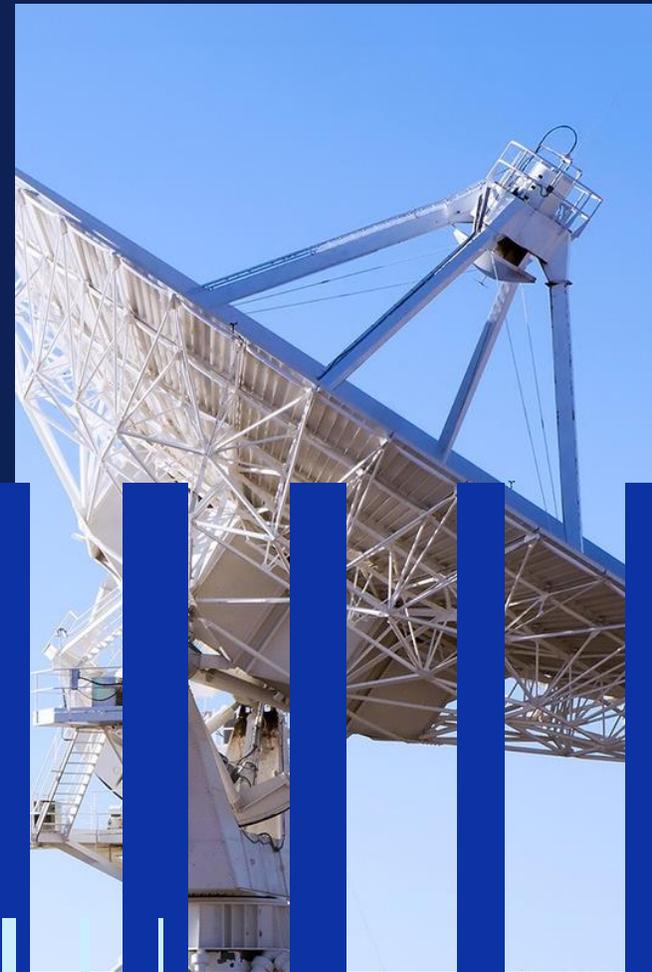
Continuous Modernization



Edge Processing



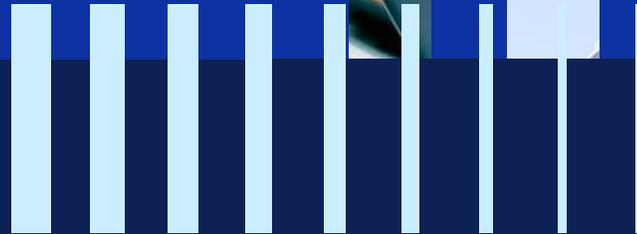
Future-Ready Data Center



Dell PowerEdge

Accelerate transformation anywhere

Purpose-built | Intelligent | Cyber Resilient



PowerEdge Servers

Purpose-built | Intelligent | Cyber resilient

M-Series

Ultimate Density

XE-Series

AI Powerhouse for
Extreme Acceleration

T-Series

Enterprise-Class
Computing, Anywhere

XR-Series

Engineered for Extreme
Environments

R-Series

The Ultimate Data
Center Workhorse



Where Innovation and Performance Converge

Unmatched Synergy: Dell's Unique Strengths Realized in PowerEdge



Power & cooling

Industry-leading energy-efficient designs and cooling solutions.

Services

End-to-end services for deployment, management, and scaling IT infrastructure.

Breakthroughs

Leading in patented innovations that enhance AI, thermal efficiency, and system performance.

Security

Secure your servers with Dell's advanced, end-to-end protections, safeguarding data and infrastructure at every stage.

Automation

Transform IT into a competitive advantage with Dell's automation solutions, enhancing speed, agility, and cost-efficiency.

Supply Chain

Ensure trusted, resilient IT infrastructure with Dell's secure, end-to-end supply chain solutions.

Building the Future of IT

How Dell is shaping the future for all customers



Future-ready infrastructure

Preparing for the next wave of technology, from AI at scale to edge computing.

Customer-centric design

Anticipating customer needs before they arise, with a unified approach across all segments.

TRUSTED

#1



x86 server \$
31 consecutive quarters¹

x86 server units
34 consecutive quarters²

Mainstream server \$
31 consecutive quarters

Mainstream server units
34 consecutive quarters



INTELLIGENT

Up to

\$50k

Savings via power and management optimization³

80%

of PowerEdge servers achieve EPEAT Climate+ designation⁴

Up to

110mi

Less time to manage per 100 servers⁵

Industry leading intelligent management
iDRAC 10 integrated controller & OpenManage Enterprise

SECURE

Factory-to-Site Assurance with **Secure component verification**

Built-in Security



Secure supply chain



Secure server lifecycle



Root of Trust and end-to-end verified boot resilience



Data protection

3.5x

More security capability⁶

Zero Trust

Adoption capable

POWEREDGE



¹ Source: [Dell analysis based on IDC data]

² Source: [Dell analysis based on IDC data]

³ Comparison done Dell on Dell. Savings based on national figure.]

⁴ Based on internal analysis and currently shipping products, September 2023. EPEAT registered where applicable. EPEAT registration varies by country. See www.epeat.net for registration status and tier levels by country.]

^{5&6} Based on a Principled Technologies report commissioned by Dell Technologies, "Increase security, sustainability, and efficiency with robust Dell management tools compared to the Supermicro management portfolio", April 2024. Comparing Dell iDRAC9 vs Supermicro IPMI.

PURPOSE BUILT

The leader in AI infrastructure

As noted in the Forrester® AI Infrastructure Wave

Ready for
**power-heavy
AI Workloads**



Up to
73%
Boost in power
efficiency¹

Groundbreaking performance

A single PowerEdge server can do the work of 7 older servers, with 2/3 the power consumption²

SUSTAINABLE

Engineered for efficiency

PowerEdge servers have reduced Energy Intensity (EI) by **83%** over the past 8 years³

Efficient

Up to **73%** boost in power efficiency⁴

AI

Fastest growing AI platform

Dell PowerEdge XE9680

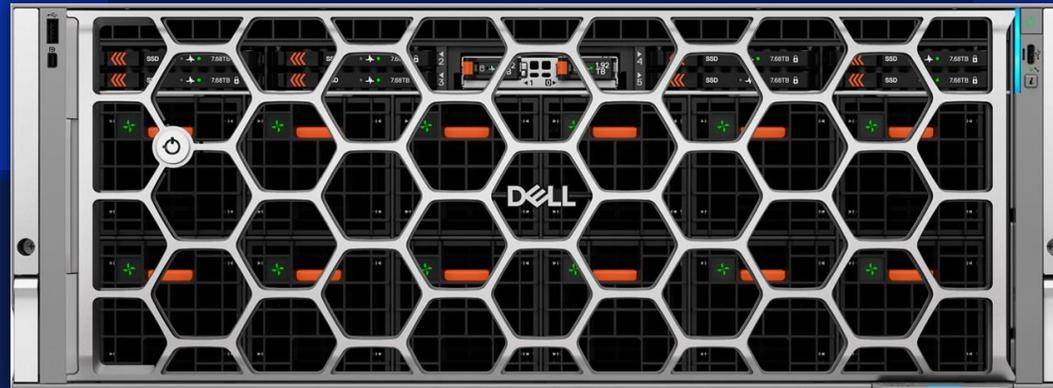
3X better
GPU density

With the Liquid Cooled
Dell PowerEdge
XE9680L⁵



Over previous generations
in MLPerf 4.0® with the
Dell AI Factory with
NVIDIA⁶

POWEREDGE



¹ Source: [Testing was conducted by Dell in June of 2023. Performed on PowerEdge XE9680 with 8x Nvidia H100 SXM4-80GB (latest gen) and PowerEdge XE9680 with 8x Nvidia A100-SXM-80GB (previous gen). MLPerf™ 3.0 RetinaNet Training benchmark was used. Increase in power efficiency for natural language model training specifically.]

² Source: [Based on Dell analysis comparing the SPECint and SPECfp scores of the AMD EPYC 5th Gen 9965 in a Dell R7725 (2980 and 2350) with the same scores for an Intel Xeon 8280 in a Dell PowerEdge R740XD (375 and 296). The ratio of the scores shows that 7 of the R740xd servers would give a total score similar to that for the single R7725 as configured above. The CPUs in a single R7725 would have a total TDP of 1000W (2x500W). The CPUs in 7x R740XD's would have a total TDP of 2870W (2*205*7) where each Intel Xeon 8280 has a TDP of 205W. This represents a CPU power reduction of 65%. Data accurate as of 10/2/2024. Actual performance will vary.]

³ Source: [<https://www.dell.com/en-uk/dt/microsites/sustainable-servers.htm>]

⁴ Source: [13- Based on Dell internal calculations using AMD Stream benchmark achieved on a Dell PowerEdge C6615 and a TDP of 200W with AMD EPYC 8534P 64-Core processors compared to a Dell PowerEdge 1S server and a TDP 280W with AMD EPYC 9534P 64-Core processors. Actual performance will vary.]

⁵ Source: [CLM-012191 PowerEdge XE9680L is 33% more dense than a PowerEdge XE9680 server in terms of vertical rack space utilization. Disclosure The direct liquid cooled Dell PowerEdge XE9680L is 4 RU vs. the 6 RU XE9680]

⁶ Source: [CLM-012631 Dell PowerEdge XE9680 with 8x Nvidia H100 GPUs trains the BERT Large NLP model 6x faster (84% less time) than the PowerEdge XE8545 with 4x Nvidia A100 GPUs]

Complementary BUs

Security

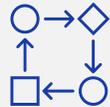
PowerEdge Security: Confidence to Innovate

Businesses need to protect data, ensure resilience, and simplify compliance—without added complexity. Dell PowerEdge servers deliver built-in security, automating defense and enabling a Zero Trust approach so organizations can innovate without compromise.



Seamless Protection

PowerEdge servers integrate protection at every level, reducing complexity while safeguarding critical applications and data.



Uninterrupted Business

Minimize risk and avoid downtime with proactive security, automated threat response, and built-in resilience to keep your operations running.



Uncompromising Security

Adopt a proactive security stance with Zero Trust principles, ensuring strict access controls, continuous verification, and seamless compliance to protect your infrastructure.

Security for PowerEdge

External

- [PowerEdge Security](#)
- [Cyber Resilient Security in Dell PowerEdge Servers](#)
- [Secured Component Verification \(SCV\)](#)
- [SCV Video](#)
- [Security eBook](#)
- [PowerEdge and Intel TDX Infographic](#)
- [PowerEdge and AMD Infographic](#)

Networking

Embrace Innovation, Streamline the Complex

Simplified design, management and monitoring of powerful, open, standards-based Ethernet fabrics capable of handling modern workloads like Generative AI.



Scalable Performance

Hardware and software solutions designed to optimize efficiency and adapt to the needs of growing businesses. Our portfolio ensures reliability and flexibility to confidently support evolving workloads.



Open Innovation

With an open, standards-based approach, Dell Networking fosters innovation by supporting multi-vendor environments, giving customers the flexibility to tailor their solutions to their unique needs.



Automation & Observability

Simplify network management with advanced automation and deep analytics, ensuring tasks are performed with precision and efficiency. These capabilities provide real-time insights, reduce downtime, and streamline complex network operations.

Dell Networking Solutions

External

- [Customer Presentation: Delivering the Future of Connectivity](#)
- [Data Sheet: Dell Enterprise SONiC](#)
- [Data Sheet: SmartFabric Manager](#)
- [Customer Story: Hot Aisle](#)
- [ESG Report: Enabling Ethernet-powered Solutions for GenAI](#)

Automation

Unlocking Efficiency with Intelligent IT Automation

By automating critical IT operations, businesses can reduce manual effort, prevent disruptions before they occur, and optimize resources for cost savings. Dell PowerEdge management tools empower IT teams to work smarter, ensuring systems remain secure, scalable, and high-performing without unnecessary complexity.



Efficiency and Time Savings

Automating server deployment and updates eliminates time-consuming manual tasks, allowing IT teams to focus on strategic initiatives instead of routine maintenance.



Enhanced Performance and Reliability

AI-driven analytics predict failures before they disrupt operations, while automated troubleshooting and self-healing keeps business operations running smoothly.



Reduce complexity

With centralized control and AI-driven insights, IT teams can manage environments more efficiently, reducing complexity while maintaining security, performance, and scalability.

Automation for PowerEdge

External

- [Server Management Solutions](#)
- [OpenManage Enterprise Brochure](#)
- [OpenManage Portfolio Licensing Guide](#)
- [AIOps Infrastructure Observability](#)
- [Video - Cambridge University](#)

Smart Cooling

From Necessity to Competitive Advantage

Value Statement: Take control of your data center's thermal management with AI-driven optimization and advanced instrumentation. SmartCooling reduces energy use and enhances reliability, helping you tackle high-performance workloads and scale modern data centers efficiently and sustainably.



Improved System Performance and Reliability

Optimize performance and reliability with advanced heat management and real-time thermal precision. Prevent bottlenecks, safeguard components, and ensure seamless operation for AI, HPC, and high-performance workloads.



Lower Costs

Reduce costs with Dell SmartCooling that continuously monitors and optimizes energy usage. Maintain peak performance for high-demand workloads with a sustainable, cost-effective solution tailored to modern data centers.



Scalability for Future Growth

Enable future growth with scalable solutions that adapt to expanding workloads. Leverage advanced cooling technologies to prevent bottlenecks, safeguard systems, and ensure seamless performance for AI, HPC, and high-demand environments.

SmartCooling for the modern data center

External

- [Customer Presentation: Services for PowerEdge Servers](#)
- [SmartCooling Brochure: Liquid Cooling Capabilities](#)
- [SmartCooling Brochure](#)
- [SmartCooling Point of View](#)
- [Solutions Brief: OpenManage Enterprise Power Manager](#)
- [Dell Services for Sustainable Data Centers](#)

Services

Ignite PowerEdge Innovation

Extend the life and value of PowerEdge servers with Dell Technologies Services. From AI planning to expert deployment and proactive support, our offerings simplify technology so you can focus on your business.



Unlock advantage

Boost innovation and efficiency with Dell Professional Services, offering AI-driven workflows, multi cloud flexibility, advanced data solutions, and sustainable IT strategies tailored to your business.



Maximize agility

Enhance your business with Dell's consulting, residency, and security services to optimize your data center and ensure smooth server performance while accessing flexible payment options designed to fit your business requirements.



Reduce complexity

Realize business efficiency and enjoy peace of mind with Dell's rapid server deployment, proactive support, predictive maintenance, and managed services, all designed to ensure seamless server performance.

Services for PowerEdge

External

- [Customer Presentation: Services for PowerEdge Servers](#)
- [Brochure: Services for Server](#)
- [Data Sheet: ProDeploy for PowerEdge](#)
- [Principled Technologies Report: ProDeploy for Servers](#)

Customer References

Leveraging Customer Stories to Drive Success

Customer stories showcase the impact and successes of Dell Technologies' solutions, building trust and inspiring potential clients. Leverage these experiences to drive engagement and sales growth



Showcase Real-World Success

Highlight how Dell Technologies' solutions have driven tangible results for customers. Use specific examples to demonstrate the impact on productivity, efficiency, and overall business growth.



Build Trust and Credibility

Emphasize the importance of customer stories in establishing trust with potential clients. Real-world video testimonials and case studies provide authentic proof of the value and reliability of Dell Technologies' solutions and services.



Inspire and Engage Prospects

Use customer stories to help prospects envision similar successes for their own businesses. Engaging narratives can inspire confidence and motivate potential clients to take the next step with Dell Technologies.

Customer References for PowerEdge

External

- [Customer Stories on Dell.com](#)
- [PowerEdge and Networking Customer Overview Slides](#)

Product Content

PowerEdge Servers

Purpose-built | Intelligent | Cyber resilient

M-Series

Ultimate Density

XE-Series

AI Powerhouse for
Extreme Acceleration

T-Series

Enterprise-Class
Computing, Anywhere

XR-Series

Engineered for Extreme
Environments

R-Series

The Ultimate Data
Center Workhorse





PowerEdge XE-Series Family

Purpose-Built for AI Performance

Optimized for acceleration with advanced cooling capabilities



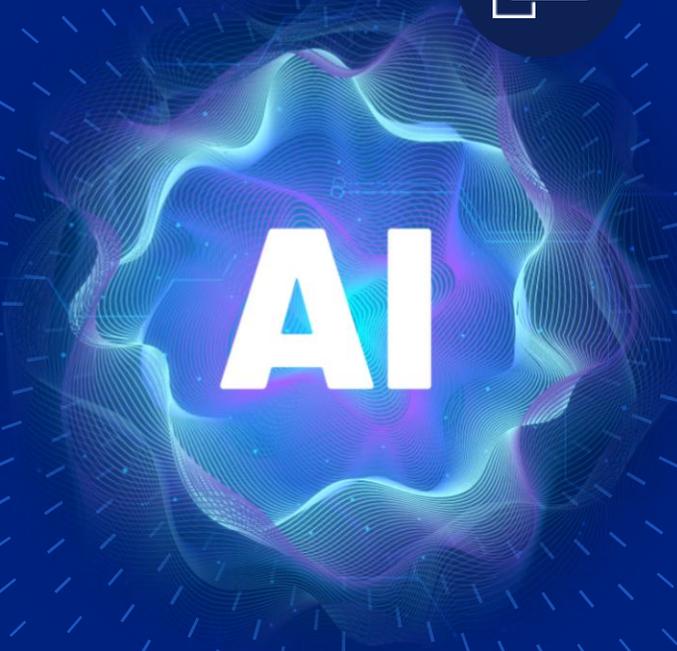
3X better GPU density

With the Liquid Cooled Dell PowerEdge XE9680L¹



Up to 6X boost

Over previous generations in MLPerf 3.0[®] with the Dell AI Factory with NVIDIA²



Flexible Integrated Rack Scalable Systems

Modular infrastructure, at any scale



Comprehensive datacenter assessment



Design and architecture



Build and configuration



Test clusters and validate nodes



Deploy, connect and test again



One-call support



Unmatched AI acceleration



Intelligent cooling efficiency



Rapid deployment & integration

¹[CLM-012190] The direct liquid cooled Dell PowerEdge XE9680L is 4 RU vs. the 6 RU XE9680

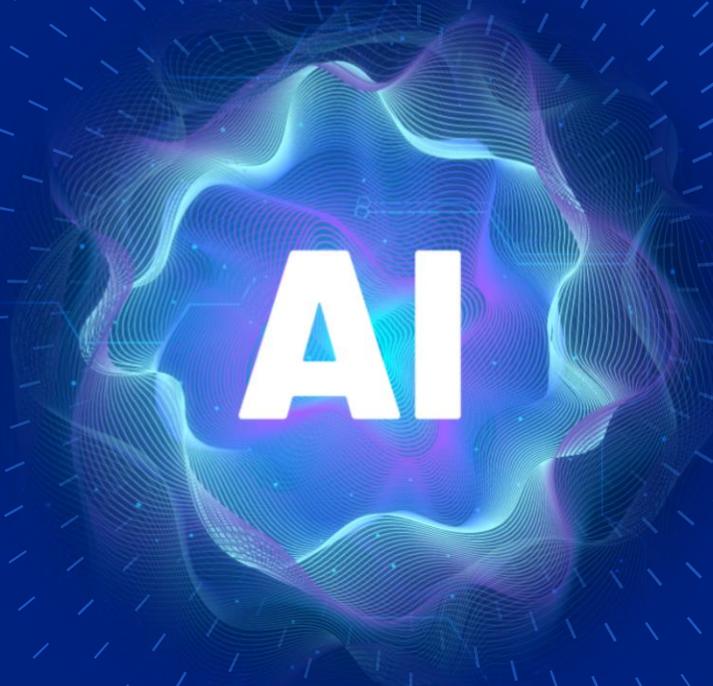
²[CLM-008745] Dell PowerEdge XE9680 with 8x Nvidia H100 GPUs trains the BERT Large NLP model 6x faster (84% less time) than the PowerEdge XE8545 with 4x Nvidia A100 GPUs

Latest AI Servers

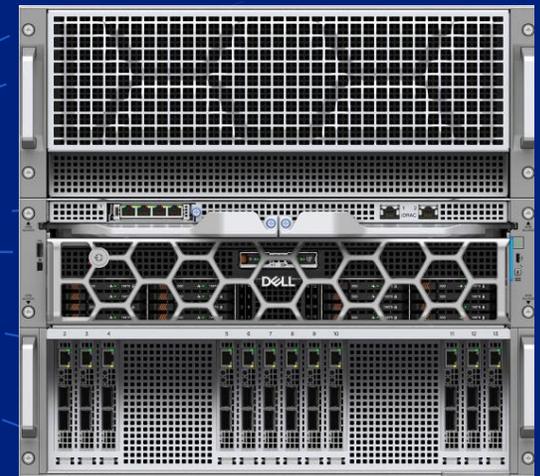
Capability	Specification
Processor	AMD, Intel, or NVIDIA CPUs
GPU	Multiple form factors from AMD, Intel, and NVIDIA
Memory	Up to DDR5 system and HBM3e GPU RAM
Storage	Multiple NVMe and SAS/SATA SSD drive options
Networking	High-speed Ethernet and InfiniBand optimized networking options
Power Supply	Redundant, high-efficiency power supplies
Cooling	Advanced air and liquid cooling options
Expansion Slots	PCIe Gen5 slots for additional cards
Management	Dell iDRAC and OpenManage systems management suite
Form Factor	Both traditional and sled-based rack-mounted server form factors

Ideal for

- Accelerated AI, ML, and data-intensive tasks.
- Seamless handling of large datasets and memory-intensive applications
- Scalable and fast data access
- Faster data transfer and reduced latency
- Simplified and efficient system monitoring and management.
- High-performance computing



XE7740 / XE7745



XE9780 / XE9785



XE9780L / XE9785L

For more detailed specifications visit
[Dell.com](https://www.dell.com)

Rack-scale AI: Silicon Diversity, High Density, and Scalability with Next-gen Cooling Technologies

Power the most demanding AI workloads and increase energy efficiency. Reduce deployment costs and enable large-scale growth with our wide-ranging portfolio:

- ✓ 19" Racks or 21" OCP Standards based Racks
- ✓ Air-cooled, DLC, or Hybrid
- ✓ Diverse compute portfolio offers the latest processors and accelerators



- Re-imagine Data Center Design with High Density Solutions for More Performance in Reduced Space
- Advanced Thermal Management for Energy Efficiency

- ✓ Expert Datacenter Assessment
- ✓ Custom Rack Integration
- ✓ One-call Support for Entire Rack



3x

Dell rack integration services are three times faster than DIY

144

Leading GPU density per standard rack



- Generate ROI Immediately with Rack Scale Factory Integration and Support to Reduce Deployment Time and Cost

PowerEdge XE9680

2 Socket Capable

- Intel® Xeon® 4 or 5 processors with up to 64 cores per processor
- 6U air-cooled, up to 35C ambient
- 1200mm rack capable

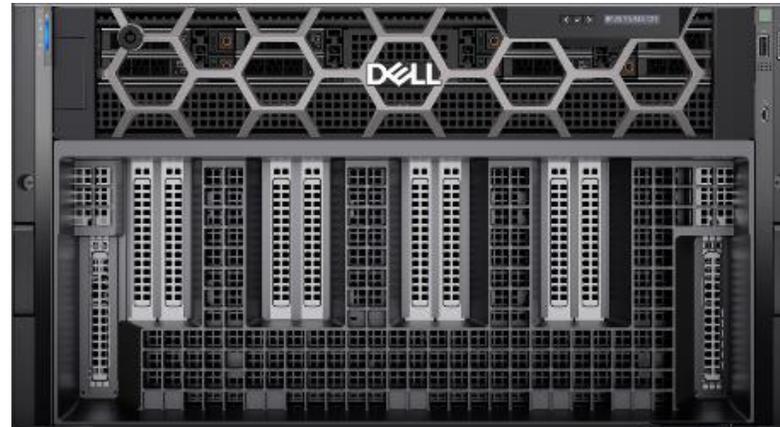
Support for high-speed and memory capacity

- Up to 32 DDR5 DIMMs
- Up to 5600 MT/s (1DPC) or 4400 MT/s (2DPC)

AI
Large Model Training

System Management

- iDRAC
- OpenManage Enterprise



I/O

- 10 x 16 PCIe Gen5 slots
- One OCP NIC 3.0
- 2 x 1GbE LOM

Support for up to 16 Drives

- Up to 8 SAS/SATA or NVMe Gen4 or 16x E3.S
- Rear Hot-Plug BOSS N-1 (2 x M.2 NVMe) for boot (optional)
- SW RAID/PERC12 support

Optimized for silicon diversity

- 8x AMD Instinct MI300X OAM 750W 192 GB AI Accelerators or
- 8x Nvidia H100 SXM 700W 80GB GPUs or
- 8x Nvidia H200 SXM 700W 141GB AI GPUs or
- 8x Intel Gaudi 3 850W 18GB AI Accelerators (coming soon)
- Full GPU to GPU interconnectivity

Technical Specifications – XE8545, XE8640, XE9680

Features	PowerEdge XE8545	PowerEdge XE8640	PowerEdge XE9680
CPU	Up to two 3 rd Generation AMD EPYC™ processors with up to 64 cores per processor Support for up to 2 x 280W processors	Up to two 4 th or 5 th Generation Intel® Xeon® Scalable processors with up to 56 cores per processor, Support for up to 2 x 350W processors	Up to two 4 th or 5 th Generation Intel® Xeon® Scalable processors with up to 56 cores per processor Support for up to 2 x 350W processors
Memory	16x or 32 x DDR4 DIMM Speed: Up to 3200 MT/s	Up to 32 x DDR5 RDIMMs DIMM Speed: Up to 4800 MT/s	Up to 32 x DDR5 RDIMMs DIMM Speed: Up to 4800 MT/s
Storage (Chassis options)	Up to 10x 2.5" Hot Plug SAS/SATA or up to 8x NVMe BOSS	Up to 8 E3.S Gen5 NVMe or SAS/NVME 2.5" SSDs BOSS-N1 (2 x M.2 NVMe) for boot	Up to 16 E3.S Gen5 NVMe or 8 2.5" SAS/NVMe SSDs Rear Hot-Plug BOSS-N1 (2 x M.2 NVMe) for boot
Storage Controller	S1.5, H745, H755	PERC12, SW RAID	PERC12, SW RAID
Network	Optional OCP NIC 3.0, Fixed 2 x 1GbE LOM	Optional OCP NIC 3.0, Optional 2 x 1GbE LOM	Optional OCP NIC 3.0, Optional 2 x 1GbE LOM
PCIe slots	1 x PCIe Gen4 LP (x16) 1 x PCIe Gen4 FH (x16) 1 x PCIe Gen4 FH (x16) or 2 x PCIe Gen4 FH (x8)	4 x PCIe Gen5 Full Height (x16)	10 x PCIe Gen5 Full Height (x16)
GPU	4 x A100 GPUs with NVLink. Options: 40GB/400W or 80GB/500W	4 x H100 700W SXM NVLink GPUs	8 x MI300X 750W OAM XGI AI Accelerators 8 x H100 700W SXM NVLink GPUs 8 x H200 700W SXM NVLink GPUs 8 x Gaudi 3 850W OAM RoCE AI Accelerators (coming soon)
Integrated Ports	Front: 1 x USB 2.0, 1 x iDRACDirect micro-USB + front VGA Rear: 1 x USB 3.0 + 1 x USB 2.0, Dedicated iDRACport, VGA	Front: 1 x USB 2.0, 1 x iDRACDirect micro-USB + front VGA Rear: 1 x USB 3.0 + 1 x USB 2.0, Dedicated iDRACport, VGA	Front: 1 x USB 2.0, 1 x iDRACDirect micro-USB + front VGA Rear: 1 x USB 3.0 + 1 x USB 2.0, Dedicated iDRACport, VGA
System Management	iDRAC9 Enterprise, Datacenter license options; OpenManage Enterprise and Plugins (Power Manager, SupportAssist, and Update Manager) iDRACDirect, Quick Sync 2.0	iDRAC9 Express (base), Enterprise, Datacenter Full Support; Open Manage Enterprise and Plugins (Power Manager, SupportAssist, and Update Manager) iDRACDirect	iDRAC9 Express (base), Enterprise, Datacenter Full Support; Open Manage Enterprise and Plugins (Power Manager, SupportAssist, and Update Manager) iDRACDirect
High Availability	Hot Plug/RAID controlled drives, BOSS, PSUs	Hot Plug/RAID controlled drives, BOSS-N1, PSUs	Hot Plug/RAID controlled drives, BOSS-N1, PSUs
Power Supplies	2 + 2 2400W Redundant Hot Plug	4 x 2800W Titanium 208-240Vac PSUs with 3+1 (Full Redundancy) 2+2 FTR (Fault Tolerant Redundancy)	6x 2800W Titanium 208-240Vac PSUs with 5+1 (Full Redundancy) 3+3 FTR (Fault Tolerant Redundancy)
Thermals	Air Cooled Up to 35C	Air cooled via internal Liquid Assist Air Cooling up to 35C	Air Cooled up to 35C
Dimensions	H x W x D: 4U x 477mm x 810mm	H x W x D: 4U x 482mm x 866mm (1070mm Rack Compliant)	H x W x D: 6U x 482mm x 1001mm (1200mm Rack Compliant)
Form Factor	4U Rack Server	4U Rack Server	6U Rack Server
Operating Systems	Ubuntu, RHEL, SLES	Ubuntu, RHEL, SLES	Ubuntu, RHEL, SLES

PowerEdge XE9680L

2 Socket Capable

- Two Intel® Xeon® 5 processors with up to 64 cores per processor
- 4U direct liquid cooled CPUs, GPUs, and NVLink switches
- 1200mm rack capable

Support for high-speed and memory capacity

- Up to 32 DDR5 DIMMs
- Up to 5600 MT/s (1DPC) or 4400 MT/s (2DPC)

AI

Large Model Training,
Fine-Tuning and
Large-Scale Inferencing



I/O

- 12 x 16 PCIe Gen5 slots
- One OCP NIC 3.0
- 2 x 1GbE LOM

System Management

- iDRAC
- OpenManage Enterprise

Support for up to 8 Drives

- Up to 8 NVMe Gen4
- Rear Hot-Plug BOSS N-1 (2 x M.2 NVMe) for boot (optional)

Accelerator Optimized

- 8x Nvidia H200 SXM 700W 141GB GPUs or
- 8x Nvidia B200 SXM 1000W 180GB GPUs
- Full GPU to GPU interconnectivity

Technical Specifications – XE9680L

Features	PowerEdge XE9680L
Chassis FF	4U rack, 1200mm rack capable
CPU	Two 5 th Generation Intel® Xeon® Scalable processors with up to 64 cores per processor Up to 350W TDP
Memory	DDR5: Up to 32 x DDR5 RDIMMs (4TB) DIMM Speed: Up to 5600 MT/s (1DPC) or 4400MT/s (2DPC)
Accelerators	8x Nvidia H200 SXM 700W 141GB GPUs or 8x Nvidia B200 SXM 1000W 180GB GPUs
Front Storage	8x 2.5" NVMe
Boot Storage	Hot-Plug BOSS N-1 (2 x M.2 NVMe) for boot (optional)
Networking	2x 1GbE LOM Gen5 x8 OCP
PCIe Cards	12x PCIe Gen5 x16 Slots Full Height
PSU	Titanium: 2800W (H200 only), 3000W (B200 only), 3200W 277Vac (available in US only post RTS) 3+3 FTR or 5+1 PSU redundancy
Management	16 th generation iDRAC9
Integrated Ports	Front Ports 1 x USB 2.0; 1 x iDRAC Direct (Micro-AB USB) port ; 1 x VGA Rear Ports 1 x USB 2.0; 1 x iDRAC Direct Ethernet port; 1 x USB 3.0
Cooling	Direct Liquid Cooling CPUs, GPUs, and NVLink switches
Operating Systems	Ubuntu and RHEL (post RTS)

PowerEdge XE9685L

2 Socket Capable

- Two SP5 AMD EPYC™ 9005 Series Processors with up to 192 cores per processor
- 4U direct liquid cooled CPUs, GPUs, and NVLink switches
- 1200mm rack capable

Support for high-speed and memory capacity

- 24 DDR5 DIMMs
- 6400 MT/s (1DPC)

AI

Large Model Training,
Fine-Tuning and
Large-Scale Inferencing

System Management

- iDRAC
- OpenManage Enterprise



I/O

- 12 x 16 PCIe Gen5 slots
- One OCP NIC 3.0
- 2 x 1GbE LOM

Support for up to 8 Drives

- Up to 8 NVMe Gen4
- Rear Hot-Plug BOSS N-1 (2 x M.2 NVMe) for boot (optional)

Accelerator Optimized

- 8x Nvidia B200 SXM 1000W 180GB GPUs
- Full GPU to GPU interconnectivity

Technical Specifications – XE9685L

Features	PowerEdge XE9685L
Chassis FF	4U rack, 1200mm rack capable
CPU	Two 5th Generation AMD EPYC™ processors, up to 192 cores per processor Up to 500W TDP
Memory	DDR5: 24 x DDR5 RDIMMs (max 3TB) DIMM Speed: 6400 MT/s (1DPC)
Accelerators	8x Nvidia B200 SXM 1000W 180GB GPUs
Front Storage	8x 2.5" NVMe
Boot Storage	Hot-Plug BOSS N-1 (2 x M.2 NVMe) for boot (optional)
Networking	2x 1GbE LOM Gen5 x8 OCP
PCIe Cards	12x PCIe Gen5 x16 Slots Full Height
PSU	Titanium: 3000W, 3200W 277Vac (available in US only post RTS) 3+3 FTR or 5+1 PSU redundancy
Management	16 th generation iDRAC9
Integrated Ports	Front Ports 1 x USB 2.0; 1 x iDRAC Direct (Micro-AB USB) port ; 1 x VGA Rear Ports 1 x USB 2.0; 1 x iDRAC Direct Ethernet port; 1 x USB 3.0
Cooling	Direct Liquid Cooling CPUs, GPUs, and NVLink switches
Operating Systems	Ubuntu and RHEL (post RTS)

PowerEdge XE9780

2 Socket Capable

- 10U, 1200mm rack capable
- Dual Intel® Xeon® 6

Support for up to 16 drives

- 16x E3.s or 10x U.2 direct attach
- BOSS capable



GPU Optimized

- 8-way NVIDIA HGX B300 NVL16
- 1:1+ GPU:NIC ratio
- GPU Direct RDMA capable

Flexible I/O

- 8x OSFP CX8 + 4x PCIe Gen5x16 FH
- One OCP 3.0 slot

Support for high-speed & memory capacity

- 32 DDR5 DIMMs

System Management

- iDRAC
- OpenManage Enterprise

PowerEdge XE9785

2 Socket Capable

- 10U, 1200mm rack capable
- 5th Gen AMD EPYC processors

System Management

- iDRAC
- OpenManage Enterprise

Support for up to 16 drives

- 16x E3.s or 10x U.2 direct attach
- BOSS capable



MI350X Shown

GPU Optimized

- 8-way NVIDIA HGX™ B300 NVL16, AMD Instinct™ MI350X series
- 1:1+ GPU:NIC ratio
- GPU Direct RDMA capable

Flexible I/O

- B300: 8x OSFP CX8 + 4x PCIe Gen5 x16 FH
- MI350X: 12x PCIe Gen5x16 FH
- One OCP 3.0 slot

Support for high-speed & memory capacity

- 24 DDR5 DIMMs

XE9680 vs XE9780/5 Feature Compare

Feature Category	XE9680	XE9780/XE9785
Processor	<ul style="list-style-type: none"> 2x Intel EMR CPUs (up to 64C), up to 350W each 	<ul style="list-style-type: none"> 2x Intel GNR-SP (up to 86C), up to 500W each [or] 2x AMD Turin CPUs (up to 192C), up to 500W each
GPU	<ul style="list-style-type: none"> Nvidia H100, H200 	<ul style="list-style-type: none"> XE9780: NVIDIA B300 XE9785: NVIDIA B300, AMD MI350X
Chassis FF	<ul style="list-style-type: none"> 6U, 19" EIA Rack form factor 	<ul style="list-style-type: none"> 10U, 19" EIA Rack form factor
Networking	<ul style="list-style-type: none"> 2x 1 GbE LOM 1x OCP 3.0 Gen5 x8 10x Gen5 x16 FHHL cards 	<ul style="list-style-type: none"> No LOM 1x OCP 3.0 Gen5 x8 B300: 8x CX8 (default) + 4x Gen5 x16 FHHL cards MI355X: 12x Gen5 x16 FHHL cards
USB & Other I/O	<ul style="list-style-type: none"> Front: 1x USB 2.0 , 1x iDRAC Direct Micro-AB USB, 1x VGA Rear: 1x USB 2.0, 1x iDRAC Direct RJ-45, 1x USB3, 1x VGA 	<ul style="list-style-type: none"> DC-SCM: 1x VGA, 2x USB Type-A, iDRAC Direct RJ-45; USB in right and left ear
Memory	<ul style="list-style-type: none"> XE9680: 32x DDR5 DIMMs, RDIMM @5600MT/s (2DPC) 	<ul style="list-style-type: none"> XE9780 GNR-SP: 32x DDR5 DIMMs @ 6400+ MT/s (2DPC) XE9785 5th Gen AMD EPYC processors: 24x DDR5 DIMMs @ 6400+ MT/s (1DPC)
Storage	<ul style="list-style-type: none"> 8x U.2 NVMe Gen4 	<ul style="list-style-type: none"> Up to 10x U.2 Gen5 [or] Up to 16x E3.S
Storage Controller	<ul style="list-style-type: none"> PERC on SAS/SATA only (NVMe direct attach) OS RAID 	<ul style="list-style-type: none"> OS RAID only
Management	<ul style="list-style-type: none"> 16th generation iDRAC 	<ul style="list-style-type: none"> 17th generation iDRAC
OS	<ul style="list-style-type: none"> RHEL, Ubuntu 	<ul style="list-style-type: none"> RHEL, Ubuntu
Boot Drives	<ul style="list-style-type: none"> 16th generation BOSS-N1, 2x M.2 (Front panel accessible) 	<ul style="list-style-type: none"> 17th generation BOSS-N1, 2x M.2 (Internal)
HA Support	<ul style="list-style-type: none"> Hot plug drives, hot-plug 60mm fans, hot plug N+1 PSU, BOSS externally hot pluggable M.2 	<ul style="list-style-type: none"> Hot plug drives, hot-plug N+N 3200W PSUs, hot-plug 60mm fans, BOSS externally hot pluggable M.2
Power	<ul style="list-style-type: none"> 6 x 2800W PSUs; Power redundancy: N+1 	<ul style="list-style-type: none"> 12 x 3200W PSUs; Power redundancy: N+N
Thermal	<ul style="list-style-type: none"> 5C to 35C/ASHRAE A2 inlet 	<ul style="list-style-type: none"> 5C to 35C/ASHRAE A2 inlet
Acoustics	<ul style="list-style-type: none"> Tier 6 	<ul style="list-style-type: none"> Tier 6

PowerEdge XE9780L

2 Socket CPUs

- Intel Granite Rapids SP
- Intel Granite Rapids AP

Density Optimized

- 30U compute nodes
- Up to 12 nodes in 500U rack



High speed memory

- 32x DDR5 on GNR-SP
- 24x DDR5 on GNR-AP
- Option for MCR-DIMM on GNR-AP

System Management

- iDRAC
- OpenManage Enterprise

Upto 16 drives + BOSS

- Storage: NVMe E1.S (16) and U.2 (8)
- Boot: M.2 BOSS (2) and U.2 (2)

More I/O for GPU

- 8x OSFP CX8 + 4x PCIe Gen5x16 FH
- One OCP 3.0 slot

Flexible power

- 21" ORv3 architecture
- Disaggregated power shelves
- Flexible power redundancy options (N+1/2 PSU, Feed, Grid)

PowerEdge XE9785L

2 Socket CPU

- AMD EPYC™ 5

Density Optimized

- 30U compute nodes
- Up to 12 nodes in 500U rack

High speed memory

- 24x DDR5 on 5th Gen AMD EPYC processors

Upto 16 drives + BOSS

- Storage: NVMe E1.S (16) and U.2 (8)
- Boot: M.2 BOSS (2) and U.2 (2)

System Management

- iDRAC
- OpenManage Enterprise

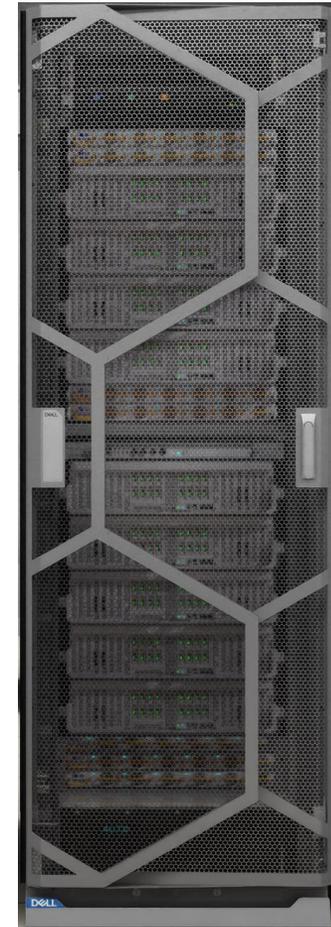
More I/O for GPU

- B300: 8x OSFP CX8 + 4x PCIe Gen5x16 FH
- MI355X: 12x PCIe Gen5x16 FH
- One OCP 3.0 slot

MI355X shown

Flexible power

- 21" ORv3 architecture
- Disaggregated power shelves
- Flexible power redundancy options (N+1/2 PSU, Feed, Grid)



XE9680L/85L vs XE9780/85L Feature Compare

Feature Category	XE9680L/XE9685L	XE9780L/XE9785L
Processor	<ul style="list-style-type: none"> 2x Intel EMR CPUs (up to 64C), up to 350W each [or] 2x AMD Turin CPUs (up to 192C), up to 500W each 	<ul style="list-style-type: none"> 2x Intel GNR-SP (up to 86C), up to 500W each [or] 2x Intel GNR-AP (up to 128C), up to 500W each [or] 2x 5ht Gen AMD processors (up to 192C), up to 500W each
GPU	<ul style="list-style-type: none"> XE9680L: Nvidia HGX H200, B200 SXM GPUs XE9780L: Nvidia HGX B200 SXM GPUs 	<ul style="list-style-type: none"> XE9780L: NVIDIA HGX B300 SXM GPU XE9785L: Nvidia HGX B300 SXM GPU, AMD MI355X OAM GPU
Chassis FF	<ul style="list-style-type: none"> 4U, 19" EIA Rack form factor with internal power supplies 	<ul style="list-style-type: none"> 30U, 21" ORv3 Rack form factor with disaggregated external power shelves
Networking	<ul style="list-style-type: none"> 2x 1 GbE LOM 1x OCP 3.0 Gen5 x8 12x Gen5 x16 FHHL cards 	<ul style="list-style-type: none"> No LOM 1x OCP 3.0 Gen5 x8 B300: 8x CX8 (default) + 4x Gen5 x16 FHHL cards MI355X: 12x Gen5 x16 FHHL cards
USB & Other I/O	<ul style="list-style-type: none"> Front: 1x USB 2.0 , 1x iDRAC Direct Micro-AB USB, 1x VGA Rear: 1x USB 2.0, 1x iDRAC Direct RJ-45, 1x USB3, 1x VGA 	<ul style="list-style-type: none"> DC-SCM: 1x VGA, 2x USB Type-A, iDRAC Direct RJ-45; one internal USB3.
Memory	<ul style="list-style-type: none"> XE9680L: 32x DDR5 DIMMs, RDIMM @5600MT/s (2DPC) XE9685L: 24x DDR5 DIMMs, RDIMM @6400MT/s (1DPC) 	<ul style="list-style-type: none"> XE9780L GNR-SP: 32x DDR5 DIMMs @ 6400+ MT/s (2DPC) XE9780L GNR-AP: 24x DDR5 DIMMs @ 6400+ MT/s [or] MCR-DIMMs @ 8800 MT/s (1DPC) XE9785L Turin: 24x DDR5 DIMMs @ 6400+ MT/s (1DPC)
Storage	<ul style="list-style-type: none"> 8x U.2 NVMe Gen4 	<ul style="list-style-type: none"> Up to 10x U.2 Gen5 (more than 8 will reduce Networking IO) [or] Up to 16x E1.S
Storage Controller	<ul style="list-style-type: none"> No PERC support OS RAID 	<ul style="list-style-type: none"> OS RAID
Management OS	<ul style="list-style-type: none"> 16th generation iDRAC RHEL, Ubuntu 	<ul style="list-style-type: none"> 17th generation iDRAC RHEL, Ubuntu
Boot Drives	<ul style="list-style-type: none"> 16th generation BOSS-N1, 2x M.2 (Front panel accessible) 	<ul style="list-style-type: none"> 17th generation BOSS-N1, 2x M.2 (Internal)
HA Support	<ul style="list-style-type: none"> Hot plug drives, hot-plug 60mm fans, hot plug N+1 PSU, BOSS externally hot pluggable M.2 	<ul style="list-style-type: none"> Hot plug drives, hot-plug 60mm fans
Power	<ul style="list-style-type: none"> Internal PSUs: 6 x 2800W PSUs for H200; 6 x 3000W PSUs for B200 Power redundancy: N+1 PSU Redundancy 	<ul style="list-style-type: none"> 33kW (6x5.5kW) Disaggregated power-shelf Power redundancy implemented through Rainwater infrastructure. N+2 PSU redundancy, 3+1 feed redundancy, 1+1 grid redundancy
Thermal	<ul style="list-style-type: none"> 10C to 35C/ASHRAE A2 inlet 	<ul style="list-style-type: none"> 10C to 35C/ASHRAE A2 inlet
Acoustics	<ul style="list-style-type: none"> Tier 6 	<ul style="list-style-type: none"> Tier 6

*Subject to Change

PowerEdge XE8712 GB200 NVL4 Dense

Product Concepts- Subject to Change

Grace Blackwell

2x NVIDIA Grace CPU (72 cores each) &
4x NVIDIA B200 GPUs per full-width node

Front I/O

- 1x OCP3 and 4x PCIe Gen 5 slots

Dense

- 1x servers per 10U

System Management

- iDRAC
- OpenManage Enterprise



Storage

- Up to 2x E3 NVMe drives
- External M.2 NVMe



Leverages Rainwater ORv3 Rack Infrastructure

- Blind mate power
- Direct liquid cooled

Technical Specifications – XE8712

Feature Category	XE8712
Processor	<ul style="list-style-type: none"> 2x Nvidia Arm Arm Neoverse V2, aka Grace (72 cores each CPU)
GPU	<ul style="list-style-type: none"> 4x 1200W B200 GPU
Chassis FF	<ul style="list-style-type: none"> 10U, 21" ORv3 Rack form factor with disaggregated external power shelves
Networking	<ul style="list-style-type: none"> 1x OCP 3.0 Gen5/6 x16 4x Gen5 x16 FHHL cards
USB & Other I/O	<ul style="list-style-type: none"> DC-SCM: 1x VGA, 1x USB Type-A, 1x USB Type-C, 1x mini DisplayPort 2x iDRAC Direct RJ-45
Memory	<ul style="list-style-type: none"> 4x 128GB SO-CAMM LPDDR5
Storage	<ul style="list-style-type: none"> 2x E3.S Gen5
Storage Controller	<ul style="list-style-type: none"> No PERC support OS RAID
Management	<ul style="list-style-type: none"> 17th generation iDRAC
OS	<ul style="list-style-type: none"> RHEL, Ubuntu, SLES
Boot Drives	<ul style="list-style-type: none"> 17th generation BOSS Flatbread, 1x M.2 (Front panel accessible)
HA Support	<ul style="list-style-type: none"> Hot plug drives, hot-plug fans,
Power	<ul style="list-style-type: none"> 33kW (6x5.5kW) Disaggregated power-shelf Power redundancy implemented through Rainwater infrastructure. N+2 PSU redundancy, 3+1 feed redundancy, 1+1 grid redundancy
Thermal	<ul style="list-style-type: none"> 10C to 35C/ASHRAE A2 inlet
Acoustics	<ul style="list-style-type: none"> Tier 6

PowerEdge XE9712 GB200 or GB300 NVL72

Grace Blackwell

- 2 Grace CPUs (72 cores each) per node
- 4 Blackwell GPUs per node

Storage

- 8x E1.S NVMe drives
- Internal M.2

ORv3 Rack

- Bus bar & power Shelves
- 33kW Powershelves



72x Blackwell GPUs acting as one

- Rack-scale, multi-node NVLink @ 1.8TB/s

I/O

- 1:1 NIC to GPU ratio for east west GPU traffic
- Bluefield3 DPUs for storage and in-band traffic

System Management

- iDRAC
- OpenManage Enterprise

PowerEdge XE7740

2 Socket Capable

- MHS-ready Intel Xeon™ ^

System Management

- iDRAC
- OpenManage Enterprise

Support for up to 8 drives

- NVMe direct attach only



GPU Optimized

- Up to 8x DW GPUs (600W)
- Up to 16x SW (75W)
- PCIe GPU vendor and type flexibility

Flexible I/O

- Up to 8 x PCIe Gen5 slots
- One OCP 3.0 slot

Support for high-speed & memory capacity

- 32 DDR5 DIMMs

PowerEdge XE7745

2 Socket Capable

- MHS-ready MB AMD EPYC™ 5th Generation

System Management

- iDRAC
- OpenManage Enterprise

Support for up to 8 drives

- NVMe direct attach only



GPU Optimized

- Up to 8x DW GPUs (600W)
- Up to 16x SW
- PCIe GPU vendor and type flexibility

Flexible I/O

- Up to 8 x PCIe Gen5 slots
- One OCP 3.0 slot

Support for high-speed & memory capacity

- 24 DDR5 DIMMs

Feature Category	R760xa 2U 2 Socket Intel; GPU optimized	XE7745
Motherboard	16th generation Casa Blanca T-shape w/ RIO/LOM/OCP	DC-MHS compliant M-FLW Type 1 w/ DC-SCM 2.0, OCP, BOSS
Chassis FF	2U	4U
Processor	2x Sapphire Rapids up to 350W, no HBM	2x AMD EPYC 5 up to 500W
CPU-CPU	3x UPI	As per HPM used
Memory	2 DPC DDR5 @4800MT/s, RDIMM only	DDR5 @ 6400MT/s
Storage Configs	6x NVMe (direct), 7x NVMe (with fPERC), or 8x SAS4 SSD (with PERC12) Diskless	8xE.3S Gen5 x4 behind PCIe switch complex Diskless
Storage Controllers	PERC11 + PERC12 (x16/x16, SAS4/NVMe)	No HBA or PERC, direct NVMe only
NDC/LOM	1GbE LOM, 1xOCP 3.0 Gen4	No LOM 1x OCP 3.0 Gen5 x8-x8 multi-root behind switch (discrete host mgmt, shared LOM)
Non-GPU PCIe Risers	4 riser slots supporting x16 Gen4 (2 each in R1 and R4 locations)	8x riser slots support x16 Gen5 FH-HL cards (attach to switch complex). 8x slots up to 150W
GPU Card Slots	4x16th generationen5 DWFL or 8 x16 Gen5 FHHL	Option 1: 8 x16 Gen5 DWFL up to 600W air-cooled with optional 4-way link bridges Option 2: 16 x15 Gen5 LP 75W air-cooled
Management	16th generation BMC, iDRAC9	DC-SCM 2.0, 17th generation BMC, iDRAC
Security	16th generation portfolio	17th generation portfolio
OS	16th generation portfolio (all)	Tier 1 Linux (RHEL, Ubuntu, SLES)
Boot Drives	16th generation BOSS N-1	17th generation BOSS N-1
USB & I/O	Front: 2x Gen2; Rear: 1x Gen2 + 1x Gen3; Optional internal	Front: USB-C Rear: VGA, 2x USB Type-A, iDRACDirect RJ-45; one internal USB3 Upsell options: DP Video + USB
HA Support	Hot plug drives, hot plug fans, hot plug redundant PSU, BOSS externally hot pluggable M.2	Hot plug drives, hot plug N+N PSU, BOSS externally hot pluggable M.2
Power	2x PSU; 1800W to 3200W; 3200W 277VAC	8x 3200W M-CRPS N+N; support for reduced population for lower power configs
Thermal	Tiers of 60mm fans, DLC support to CPU, 35C/ASHRAE A2 inlet support	35C/ASHRAE A2 inlet support; 30C for certain configs as-needed
Acoustics	Datacenter Environment (Tier 5)	Tier 6

PowerEdge R-Series Family

Performance, efficiency and resilience

Built to support today's transforming business needs and tomorrow's challenges

Unleashed performance

Top-tier power and speed for the most demanding workloads



Data Center optimization

Save space and improve power efficiency



7:1 Consolidation²



Up to 37% more drives³

Seamless management

AI-enabled iDRAC and OpenManage Enterprise ensure smarter, simpler server operations



Flexible management



AI-ready and versatile



Smart energy management

¹Based on Dell analysis of the SPECintRate scores of the AMD EPYC 5th gen 9965 CPU of 2980 in the R7725 with that of the AMD EPYC 4th gen 9754 CPU of 1790 in an R7625. Data accurate as of 10/2/2024. Actual

²Based on Dell analysis comparing the SPECint and SPECfp scores of the AMD EPYC 5th Gen 9965 in a Dell R7725 (2980 and 2350) with the same scores for an Intel Xeon 8280 in a Dell PowerEdge R740XD (375 and 296). The ratio of the scores shows that 7 of the R740xd servers would give a total score similar to that for the single R7725 as configured above. Data accurate as of 10/2/2024. Actual performance will vary

³Based on Dell analysis of specifications comparing the Dell PowerEdge R67x5 server with up to 22 E3.s drive slots with the Dell PowerEdge R66x5 servers with up to 16 E3.s drive slots. Data was collected as of 10/2/2024.

The Ultimate DataCenter Workhorse



Compute & Architecture

Architecture

Processor Options

CPU Configuration

Memory (DIMMs)

Storage & Expansion

Storage Interface

GPU Support

I/O / Expansion

Power, Cooling & Connectivity

Power Supply

Cooling Options

Networking Options

Management & Deployment

Form Factor

Management & Security

Ideal For

Use Cases

R7/R6

DC-MHS & Traditional

Intel Xeon 4th–6th Gen
AMD Epyc 4th & 5th Gen

Single & Dual CPU

Up to 32

SATA, NVMe, EDSFF

SW & DW GPUs

Front & Rear options

Redundant, High-efficiency
(Platinum/Titanium)

Air or Liquid

Onboard 1/10/25GbE; expand to
100GbE

1U & 2U Rack

iDRAC9 & 10, OpenManage Suite

Databases & Analytics, Dense
Virtualization, AI & HPC, SDS, ERP &
Critical Apps

R5/R4

DC-MHS & Traditional

Intel Xeon 4th–6th Gen

Single CPU

Up to 16

SATA, NVMe, EDSFF

SW & DW GPUs

Front & Rear options

Redundant, High-efficiency

Air

Onboard 1/10GbE; expand to 25GbE

1U & 2U Rack

iDRAC9 & 10, OpenManage Suite

General Business Apps, Entry DB &
Analytics, Edge & Distributed
Workloads, SMB

R3/R2

Traditional

Intel Xeon E-2400, Xeon 6300,
Pentium

Single CPU

Up to 4

SAS, SATA

SW GPUs

Front & Rear options

Basic redundant PSU

Air

Onboard GbE

1U Rack

iDRAC9, OpenManage Suite

ROBO/Edge, Collaboration,
Messaging, Entry DB Management

Dell PowerEdge R7725 (2U2S)

A step ahead in processing

- Powered by two AMD EPYC 5th Generation processors
- Up to 24x DDR5 RDIMMs (Up to 6TB)

I/O and connectivity

- Up to 8x PCIe slots (all Gen5)
- OCP 3.0 for network cards (dual option)



Flexible storage

- 12x 3.5" SAS/SATA
- 8x 2.5" Universal / 16x 2.5" SAS/SATA / 24x 2.5" SAS/SATA
- 16x 2.5" SAS/SATA + 8x U.2 OR 2.5" NVMe RAID
- 8x E3.S / 16x E3.S / 32x E3.S / 40x E3.S

Connectivity

- Easily connect peripherals from the front or rear using USB, Micro USB and serial connections

System Management

- iDRAC
- OpenManage Enterprise
- Additional Management frameworks :
 - Dell AI Ops
 - NativeEdge

Technical Specifications – R7625, R7725

Features	PowerEdge R7625	PowerEdge R7725
Motherboard	16th generation Dell Design	DC-MHS FLW
Chassis FF	2U rack, depth 700mm	2U rack, depth 700mm
CPU	Up to two 4th Generation AMD EPYC™ processors, up to 128 cores per processor Up to 400W (cTDP) 4x xGMI for improved performance	Two 5th Generation AMD EPYC™ processors, up to 192 cores per processor Up to 500W (cTDP) 4x xGMI for improved performance + Readiness for CXL 2.0 AIC
Memory	DDR5: Up to 24x DDR5 (6TB), 1DPC DIMM Speed: Up to 4800 MT/s	DDR5: Up to 24x DDR5 (6TB), 1DPC DIMM Speed: Up to 6400 MT/s
Accelerators	GPUs: Up to 2x DW (400W) or up to 6x SW (75W) DPUs: Up to 2x BF3 2x100GbE (150W)	GPUs: Up to 2x DW (400W & up to DW 450W UI); Up to 6x SW (75W)
Front Storage	8x 3.5" SAS/SATA / 12x 3.5" SAS/SATA / 12x 3.5" SAS/SATA + Rear 2x or 4x 2.5" or 4x E3.S 8x 2.5" Universal OR U.2 / 16x 2.5" SAS/SATA OR U.2 / 24x SAS/SATA 16x 2.5" SAS/SATA + 8x U.2 24x 2.5" SAS/SATA with 4x or 8x Universal OR 2x 2.5" OR 2x U.2 OR 4x 2.5" OR Rear 4x E3.S 24x U.2 Switched 8x E3.S / 16x E3.S / 32x E3.S	12x 3.5" SAS/SATA 8x 2.5" Universal / 16x 2.5" SAS/SATA / 24x 2.5" SAS/SATA 16x 2.5" SAS/SATA + 8x U.2 OR 2.5" NVMe RAID 8x E3.S / 16x E3.S / 32x E3.S / 40x E3.S
Rear Storage	2x or 4x 2.5" / 4x E3.S	N/A
Boot Storage	IDSDM, 16th generation NVMe BOSS	No IDSDM, 17th generation BOSS
Controllers	PERC11 / PERC12	PERC12 / PERC13 (G5 x16)
Networking	Optional LOM Riser + 1x OCP Gen4	No LOM; default one Gen5 x16 OCP and optional for second Gen5 x16 OCP
PCIe Lanes/Cards	128 lanes (4x xGMI) Up to 8x PCIe Slots (4x Gen4 + 4x Gen 5)	128 lanes (4x xGMI) Up to 8x PCIe Slots Full Gen5 (no SNAPI)
PSU	Platinum 800W, 1400W, 2400W Titanium: 1100W, 1400W 277Vac, 1800W, 2800W, 3200W 277Vac Telco: 1100W -48VDC	Platinum 800W, 1100W Titanium: 800W, 1100W, 1500W, 1500W 277Vac & HVDC, 1800W, 2400W, 3200W, 3200W 277Vac & HVDC Telco: 1400W -48VDC
Management	16th generation iDRAC9	17th generation iDRAC10
User interface	Front: 1x USB2, 1x USB2 managed (micro); VGA; Upsell: Wireless mgmt Rear: 1x USB2; 1x USB3; 1x Int USB3; VGA, iDRACDirect RJ45, Serial (RIO via slot)	Front: RCP = low cost base offer, 1x USB2.0 Type C host/managed LCP = upsells: 1) Digital video + USB 2.0 + Active bezel pogo. 2) wireless mgmt 1x Int USB3; Rear (DC-SCM) 2x USB3; VGA option, iDRACDirect RJ45, dongle serial option (no slot loss)
Cooling	Air cooling, Direct Liquid Cooling	Air cooling, Direct Liquid Cooling

*17th generation Tech Specs
subject to change

PowerEdge R7725xd

A step ahead in processing

- Powered by two AMD EPYC 5th Gen Processors

Storage-Dense Configurations

- 24x 2.5" U.2 (x4) Gen5 Direct Connect with rich I/O
- Direct Attach NVMe

Rich I/O configurations

- Up to five PCIe Gen 5
- One OCP NIC 3.0 Gen 3



Support for high-speed and memory capacity

- Up to 24 DDR5 DIMMs
- Up to 6400 MT/s (1DPC)

Connectivity

- Easily connect peripherals from the front or rear using USB, Micro USB and serial connections

System Management

- iDRAC
- OpenManage Enterprise
- Additional Management frameworks :
 - Dell AIOps
 - NativeEdge

Technical Specifications – R7725xd

Features	PowerEdge R7725xd
CPU	Two 5th Generation AMD EPYC™ processors, with up to 192C* per processor
Memory	Up to 24 x DDR5 RDIMMs DIMM Speed: Up to 6400 MT/s
Storage (Chassis options)	Front Storage: 24x 2.5" U.2 (x4) Gen 5 Rear Hot-Plug BOSS-N1 (2 x M.2 NVMe) for boot
Storage Controller	N/A – Direct Attach NVMe only
Network	1x OCP NIC 3.0 Gen 3 (x4)
PCIe slots	Up to 5 x PCIe Gen5 Full Height (x16)*
GPU	N/A
Integrated Ports	Front: 1 x USB 2.0 (Optional KVM), 1x USB 2.0 (HOST/BMC direct), 1x Mini Display port Rear: 2 x USB 3.0, 1GB dedicated BMC Ethernet port, 1xVGA
System Management	17 th generation iDRAC 10
High Availability	Hot Plug drives, BOSS-N1, PSUs
Power Supplies	Titanium: 1500W, 1800W*, 2400W*, 3200W
Thermals	Air Cooled up to 35C
Dimensions	H x W x D: 2U x 482mm x 700.7mm (w/o Bezel) (1200mm Rack Compliant)
Form Factor	2U Rack Server
Operating Systems	Ubuntu, RHEL, SLES, Windows*, VMware ESXi*

Dell PowerEdge R7715 (2U1S)

The only socket you need

- Powered by one AMD EPYC 5th Generation processors
- Up to 24x DDR5 RDIMMs (Up to 6TB)

I/O and connectivity

- Up to 8x PCIe slots (all Gen5)
- OCP 3.0 for network cards (dual option)

Flexible storage

- 2x U.2
- 12x 3.5" SAS/SATA
- 8x 2.5 Universal / 16x 2.5" SAS/SATA / 24x 2.5" SAS/SATA
- 16x 2.5" SAS/SATA + 8x U.2
- 8x E3.S / 16x E3.S / 32x E3.S / 40x E3.S



Connectivity

- Easily connect peripherals from the front or rear using USB, Micro USB and serial connections

System Management

- iDRAC
- OpenManage Enterprise
- Additional Management frameworks :
 - Dell AIOps
 - NativeEdge

Technical Specifications – R7615, R7715

Features	PowerEdge R7615	PowerEdge R7715
Motherboard	16th generation Dell Design	DC-MHS FLW
Chassis FF	2U rack, depth 700mm	2U rack, depth 700mm
CPU	One 4th Generation AMD EPYC™ processor, up to 128 cores per processor Up to 400W (cTDP)	One 5th Generation AMD EPYC™ processor, up to 160 cores per processor Up to 400W (cTDP) Readiness for CXL 2.0 AIC
Memory	DDR5: Up to 12x DDR5 RDIMM (3TB), 1DPC DIMM Speed: Up to 4800 MT/s	DDR5: Up to 24x DDR5 RDIMM (6TB), 2DPC DIMM Speed: For 1DPC, up to 5200 MT/s; for 2DPC up to 4400MT/s
Accelerators	GPUs: Up to 3x DW (400W) or up to 6x SW (75W) DPUs: Up to 2x BF3 2x100GbE (150W)	GPUs: Up to 3x DW (400W & up to DW 450W UI); Up to 6x SW (75W) DPUs: Up to 2x BF3 2x200GbE (150W)
Front Storage	8x 3.5" SAS/SATA / 12x 3.5" SAS/SATA / 12x 3.5" SAS/SATA + Rear 2x or 4x 2.5" or 4x E3.S 8x 2.5" Universal OR U.2 / 16x 2.5" SAS/SATA OR U.2 / 24x SAS/SATA 16x 2.5" SAS/SATA + 8x U.2 24x 2.5" SAS/SATA with 8x Universal OR 2x 2.5" OR 2x U.2 OR 4x 2.5" OR Rear 4x E3.S 24x U.2 Switched 8x E3.S / 16x E3.S / 32x E3.S	2x U.2 12x 3.5" SAS/SATA 8x 2.5 Universal / 16x 2.5" SAS/SATA / 24x 2.5" SAS/SATA 16x 2.5" SAS/SATA + 8x U.2 8x E3.S / 16x E3.S / 32x E3.S / 40x E3.S
Rear Storage	2x or 4x 2.5" / 4x E3.S	N/A
Boot Storage	IDSDM, 16th generation NVMe BOSS	No IDSDM, 17th generation BOSS
Controllers	PERC11 / PERC12	PERC12 / PERC13 (G5 x16)
Networking	Optional LOM Riser + 1x OCP Gen4	No LOM; default one Gen5 x16 OCP and optional for second Gen5 x16 OCP
PCIe Lanes/Cards	128 lanes Up to 8x PCIe Slots (4x Gen4 + 4x Gen 5)	128 lanes Up to 8x PCIe Slots Full Gen5 (no SNAPI)
PSU	Platinum 800W, 1400W, 2400W Titanium: 700W, 1100W, 1400W 277Vac, 1800W Telco: 1100W -48VDC	Platinum 800W, 1100W Titanium: 800W, 1100W, 1500W, 1500W 277Vac & HVDC, 1800W, 2400W, 3200W, 3200W 277Vac & HVDC Telco: 1400W -48VDC
Management	16th generation iDRAC9	17th generation iDRAC10
User interface	Front: 1x USB2, 1x USB2 managed (micro); VGA; Upsell: Wireless mgmt Rear: 1x USB2; 1x USB3; 1x Int USB3; VGA, iDRACDirect RJ45, Serial (RIO via slot)	Front: RCP = low cost base offer, 1x USB2.0 Type C host/managed LCP = upsells: 1) Digital video + USB 2.0 + Active bezel pogo. 2) wireless mgmt 1x Int USB3; Rear (DC-SCM) 2x USB3; VGA option, iDRACDirect RJ45, dongle serial option (no slot loss)
Cooling	Air cooling, Direct Liquid Cooling	Air cooling, Direct Liquid Cooling

*17th generation Tech Specs
subject to change

Dell PowerEdge R6725 (1U2S)

A step ahead in processing

- With AMD EPYC 5th Generation processors
- Up to 24x DDR5 RDIMMs (Up to 3TB)

I/O and connectivity

- Up to 3x PCIe slots (all Gen5)
- OCP 3.0 for network cards (dual option)



Flexible storage

- 4x 3.5" SAS/SATA
- 8x 2.5" Universal OR U.2 / 10x 2.5" SAS/SATA
- 10x2.5" with 4x Universal
- 8x E3.S / 16x E3.S
- 20x E3.S + Rear 2x E3.S

Connectivity

- Easily connect peripherals from the front or rear using USB, Micro USB and serial connections

System Management

- iDRAC
- OpenManage Enterprise
- Additional Management frameworks :
 - Dell AIOps
 - NativeEdge

Technical Specifications – R6625, R6725

Features	PowerEdge R6625	PowerEdge R6725
Motherboard	16th generation Dell Design	DC-MHS FLW
Chassis FF	1U rack, depth 700mm	1U rack, depth 700mm
CPU	Up to two 4th Generation AMD EPYC™ processors, up to 128 cores per processor Up to 400W (cTDP) 4x xGMI for improved performance	Two 5th Generation AMD EPYC™ processors, up to 192 cores per processor Up to 500W (cTDP) 4x xGMI for improved performance
Memory	DDR5: Up to 24 x DDR5 RDIMMs (6TB), 1DPC DIMM Speed: Up to 4800 MT/s	DDR5: Up to 24 x DDR5 RDIMMs (3TB), 1DPC DIMM Speed: Up to 6400 MT/s
Accelerators	GPUs: Up to 3x SW (75W) DPUs: Up to 2x BF3 2x100GbE (150W)	GPUs: Up to 3x SW (75W)
Front Storage	4x 3.5" SAS/SATA / 4x 3.5" SAS/SATA + Rear 2x E3.S 8x 2.5" Universal OR U.2 / 10x 2.5" SAS/SATA OR U.2 10x 2.5" SAS/SATA + Rear 2x 2.5" or 2x E3.S 10x2.5" with 4x Universal 14x E3.S 16x E3.S	4x 3.5" SAS/SATA 8x 2.5" Universal OR U.2 / 10x 2.5" SAS/SATA 10x2.5" with 4x Universal 8x E3.S / 16x E3.S 20x E3.S + Rear 2x E3.S
Rear Storage	2x E3.S G5	2x E3.S G5
Boot Storage	IDSDM, 16th generation NVMe BOSS	No IDSDM, 17th generation BOSS
Controllers	PERC11 / PERC12	PERC12 / PERC13 (G5 x16)
Networking	Optional LOM Riser + 1x OCP Gen4	No LOM; default one Gen5 x16 OCP and optional for second Gen5 x16 OCP
PCIe Lanes/Cards	128 lanes (4x xGMI) Up to 3x PCIe Slots (1x Gen4 + 2x Gen5)	128 lanes (4x xGMI) Up to 3x PCIe Slots Full Gen5 (no SNAPI)
PSU	Platinum: 800W, 1400W Titanium: 1100W, 1400W 277Vac, 1800W Telco: 1100W -48VDC	Platinum 800W, 1100W Titanium: 800W, 1100W, 1500W, 1500W 277Vac & HVDC, 1800W Telco: 1400W -48VDC
Management	16th generation iDRAC9	17th generation iDRAC10
User interface	Front: 1x USB2, 1x USB2 managed (micro); VGA; Upsell: Wireless mgmt Rear: 1x USB2; 1x USB3; 1x Int USB3; VGA, iDRACDirect RJ45, Serial(RIO via slot)	Front: RCP = low cost base offer, 1x USB2.0 Type C host/managed LCP = upsells: 1) Digital video + USB 2.0 + Active bezel pogo. 2) wireless mgmt 1x Int USB3; Rear (DC-SCM) 2x USB3; VGA option, iDRACDirect RJ45, dongle serial option (no slot loss)
Cooling	Air cooling, Direct Liquid Cooling	Air cooling, Direct Liquid Cooling

*17th generation Tech Specs
subject to change

Dell PowerEdge R6715 (1U1S)

The only socket you need

- Powered by one AMD EPYC 5th Generation processors
- Up to 24x DDR5 RDIMMs (Up to 3TB)

I/O and connectivity

- Up to 3x PCIe slots (all Gen5)
- OCP 3.0 for network cards (dual option)



Flexible storage

- 2x U.2
- 4x 3.5" SAS/SATA
- 8x 2.5" Universal OR U.2 / 10x 2.5" SAS/SATA
- 10x2.5" with 4x Universal
- 16x E3.S
- 20x E3.S + Rear 2x E3.S

Connectivity

- Easily connect peripherals from the front or rear using USB, Micro USB and serial connections

System Management

- iDRAC
- OpenManage Enterprise
- Additional Management frameworks :
 - Dell AI Ops
 - NativeEdge

Technical Specifications – R6615, R6715

Features	PowerEdge R6615	PowerEdge R6715
Motherboard	16th generation Dell Design	DC-MHS FLW
Chassis FF	1U rack, depth 700mm	1U rack, depth 700mm
CPU	One 4th Generation AMD EPYC™ processor, up to 128 cores per processor Up to 400W (cTDP)	One 5th Generation AMD EPYC™ processor, up to 160 cores per processor Up to 400W (cTDP)
Memory	DDR5: Up to 12x DDR5 RDIMM (3TB), 1DPC DIMM Speed: Up to 4800 MT/s	DDR5: Up to 24x DDR5 RDIMM (3TB), 2DPC DIMM Speed: For 1DPC, up to 5200 MT/s; for 2DPC up to 4400MT/s
Accelerators	GPUs: Up to 3x SW (75W) DPUs: Up to 2x BF3 2x100GbE (150W)	GPUs: Up to 3x SW (75W) DPUs: Up to 2x BF3 2x200GbE (150W)
Front Storage	4x 3.5" SAS/SATA / 4x 3.5" SAS/SATA + Rear 2x E3.S 8x 2.5" Universal OR U.2 / 10x 2.5" SAS/SATA OR U.2 10x 2.5" SAS/SATA + Rear 2x 2.5" or 2x E3.S 10x2.5" with 4x Universal 14x E3.S 16x E3.S	2x U.2 4x 3.5" SAS/SATA 8x 2.5" Universal OR U.2 / 10x 2.5" SAS/SATA 10x2.5" with 4x Universal 16x E3.S 20x E3.S + Rear 2x E3.S
Rear Storage	2x E3.S G5	2x E3.S G5
Boot Storage	IDSDM, 16th generation NVMe BOSS	No IDSDM, 17th generation BOSS
Controllers	PERC11 / PERC12	PERC12 / PERC13 (G5 x16)
Networking	Optional LOM Riser + 1x OCP Gen4	No LOM; default one Gen5 x16 OCP and optional for second Gen5 x16 OCP
PCIe Lanes/Cards	128 lanes Up to 3x PCIe Slots (1x Gen4 + 2x Gen5)	128 lanes Up to 3x PCIe Slots Full Gen5 (no SNAPI)
PSU	Platinum: 800W, 1400W Titanium: 700W, 1100W, 1400W 277Vac, 1800W Telco: 1100W -48VDC	Platinum 800W, 1100W Titanium: 800W, 1100W, 1500W, 1500W 277Vac & HVDC, 1800W Telco: 1400W -48VDC
Management	16th generation iDRAC9	17th generation iDRAC10
User interface	Front: 1x USB2, 1x USB2 managed (micro); VGA; Upsell: Wireless mgmt Rear: 1x USB2; 1x USB3; 1x Int USB3; VGA, iDRACDirect RJ45, Serial(RIO via slot)	Front: RCP = low cost base offer, 1x USB2.0 Type C host/managed LCP = upsells: 1) Digital video + USB 2.0 + Active bezel pogo. 2) wireless mgmt 1x Int USB3; Rear (DC-SCM) 2x USB3; VGA option, iDRACDirect RJ45, dongle serial option (no slot loss)
Cooling	Air cooling, Direct Liquid Cooling	Air cooling, Direct Liquid Cooling

*17th generation Tech Specs
subject to change

Dell PowerEdge R770

Two Socket Optimized 2U

- Powered by Intel Xeon 6 Processors:
2 socket E-Core & P-Core (6500/6700 Class) with max TDP

Flexible Storage and Cold Aisle Support

- Up to 44x E3 G5x2 NVMe Direct
- Up to 24x 2.5" SAS/SATA
- Easy deployment and services from the cold aisle
 - 16x E3 NVMe
 - Up to 2xPCIe FHHL (Gen5 x16) + 2xOCP 3.0 (Gen5 x16)
 - Front Video, Serial, BOSS, iDRACdirect, mgt LAN

Flexible I/O

- Up to 8x PCIe slots (Gen5)
- OCP 3.0 for network cards (dual option)
- Up to 2x DW GPUs



Support for high-speed & memory capacity

- Up to 32 DDR5 DIMMs
- Up to 6400 MT/s

System Management

- iDRAC
- OpenManage Enterprise
- Additional Management frameworks :
 - Dell AIOps
 - NativeEdge

Technical Specifications – R770 Series

G2G Changes

Feature	R760	R770
CPU	Sapphire Rapid (Bronze, Silver, Gold5, Gold6, Platinum), 4UPI HBM support, Emerald Rapid MLK* Liquid Cooling support	2x Xeon 6 6500/6700 Support up to 350W TDP Liquid Cooling support
Memory	32xDDR5, 4800 MT/s Readiness for CXL SCMs (e.g. Donahue Pass) C2F Persistent DRAM HBM	Up to 32x DDR5-6400 MT/s RDIMM (8TB max) 8 channel per processor, 2 DIMMs/channel 16 / 32 / 64 / 96 / 128 / 256 GB/RDIMM standard RAS CXL memory support (UI)
Storage	Up to 12 x 3.5" SAS/SATA HDD Up to 24 x 2.5" SAS/SATA HDD/SSD or NVMe SSD Up to 16 x 2.5" SAS/SATA HDD/SSD + 8 x 2.5" NVMe SSD Up to 16 x E3.S NVMe Gen5 direct attach* Up to 4 x rear 2.5" SAS/SATA HDD/SSD or NVMe SSD Up to 4 x rear E3.S NVMe Gen5* Rear BOSS-N1 (2xM.2 NVMe) for boot	Front I/O Configs: Up to 24 x 2.5" SAS/SATA HDD/SSD Up to 16 x 2.5" SAS/SATA HDD/SSD + 8 x 2.5" NVMe SSD Up to 16 x E3.S NVMe Gen5 Single PERC* Up to 32 x E3.S NVMe Gen5 DUAL PERC* Up to 40 x E3.S NVMe Gen5 direct attach* Up to 4 x rear 2.5" SAS/SATA HDD/SSD or NVMe SSD Up to 4 x rear E3.S NVMe Gen5* Rear BOSS-N1 and M.2 Interposer (2xM.2 NVMe) for boot Cold Aisle: Up to 16 x E3.S NVMe Front BOSS-N1 and M.2 Interposer (2xM.2 NVMe) for boot
Storage Controller	RAID: PERC 11 & 12, SWRAID PERC 11: HBA355i, H755N/P, H365i, H965i Chipset SATA/SW RAID: Yes Boot: BOSS NVMe rear	RAID: PERC 12 & 13 , SWRAID HBA465e , H365i, H965i, H975i Boot: BOSS Flatbread NVMe (Hot-Swap) & M.2 Interposer Front & Rear
Network	Optional 2 x 1GbE LOM, 1 x OCP 3.0	Rear: 1 / 2x x8/16 OCP Cold Aisle: 2x x16 OCP opt. Industry Standard FW
PCIe slots	Up to 8 x PCIe Slots (with up to 4 PCIe Gen5), SNAP I/O option	Rear: Up to 8 x PCIe Slots Gen5 Cold Aisle: 2x x16 FHHL Gen5
Accelerators	2x DW or 6x SW GPU and DPU	2x DW or 6x SW GPU and DPU
Integrated Ports	Front: iDRACdirect USB type-C, KVM (DP & USB type-A), Quicksync opt. Rear: USB type-A, VGA, mgt. network RJ45	Front: iDRACdirect USB type-C, KVM opt. (DP & USB type-A) Cold Aisle: 1x mgt. network RJ45, DB9 opt Rear: USB type-A, VGA, mgt. network RJ45
System Mgmt	iDRAC9 Express, Enterprise, Datacenter, and OME	iDRAC10 Express, Enterprise, Datacenter and OME
PSU	AC (Platinum): 800W, 1400W, 2400W AC (Titanium): 700W, 1100W, 1800W, 2800W LVDC @-48VDC Input: 1100W	AC (Platinum): 800W, 1100W AC (Titanium): 800W , 1100W, 1500W , 1800W, 2400W , 3200W 277VAC & HVDC (Titanium): 1500W, 3200W -48VDC NAF: 1400W
Dimensions	1U H x W x D: 42.8mm x 482mm x 809mm (without bezel)	1U H x W x D: 42.8mm x 482mm x 815mm (without bezel)
Country SiL	Tier 1, 2, and 3	Tier 1, 2, and 3

Dell PowerEdge R670

Two Socket Optimized 1U

- Powered by Intel Xeon 6 Processors:
2 socket E-Core & P-Core (6500/6700 Class) with max TDP

Flexible I/O

- Up to 3x PCIe slots (Gen5)
- OCP 3.0 for network cards (dual option)



Flexible Storage and Cold Aisle Support

- Up to 22x E3 G5x2 NVMe Direct
- Up to 10x 2.5" SAS/SATA
- Easy deployment and services from the cold aisle
 - 8x E3 NVMe
 - Up to 2xPCIe FHHL (Gen5 x16) + 2xOCP 3.0 (Gen5 x16)
 - Front Video, Serial, BOSS, iDRACdirect, mgt LAN

Support for high-speed & memory capacity

- Up to 32 DDR5 DIMMs
- Up to 6400 MT/s

System Management

- iDRAC²
- OpenManage Enterprise²
- Additional Management frameworks :
 - Dell AI Ops
 - NativeEdge

1. Coming in Calendar Year 2026
2. Licensing Tiers Apply

Technical Specifications – R670 Series

G2G Changes

Feature	R660	R670
CPU	Sapphire Rapid (Bronze, Silver, Gold5, Gold6, Platinum), 4UPI HBM support, Emerald Rapid MLK* Liquid Cooling support	2x Xeon 6 6500/6700 Support up to 350W TDP Liquid Cooling support
Memory	32xDDR5, 4800 MT/s Readiness for CXL SCMs (e.g. Donahue Pass) C2F Persistent DRAM HBM	Up to 32x DDR5-6400 MT/s RDIMM (8TB max) 8 channel per processor, 2 DIMMs/channel 16 / 32 / 64 / 96 / 128 / 256 GB/RDIMM standard RAS CXL memory support (UI)
Storage	Up to 10 x 2.5" SAS/SATA HDD/SSD; or NVMe SSD Up to 16 x E3.S NVMe Gen5 DUAL PERC* Up to 14 x E3.S NVMe Gen5 direct attach* Up to 2 x 2.5" (rear) SAS/SATA HDD/SSD; or NVMe SSD Up to 2 x E3.S(rear) NVMe Gen5* Rear BOSS-N1 (2xM.2 NVMe) for boot	Rear I/O configs: Up to 8 x 2.5" U.2 Up to 10 x 2.5" SAS/SATA HDD/SSD inc 4x Universal Up to 16 x E3.S NVMe Gen5 Single PERC* Up to 20 x E3.S NVMe Gen5 direct attach* Up to 2 x E3.S(rear) NVMe Gen5* Rear BOSS-N1 and M.2 Interposer (2xM.2 NVMe) for boot Cold Aisle: 8 E3.S NVMe Front BOSS-N1 and M.2 Interposer (2xM.2 NVMe) for boot
Storage Controller	RAID: PERC 11 & 12, SWRAID PERC 11: HBA355i, H755N/P, H365i, H965i Chipset SATA/SW RAID: Yes Boot: BOSS NVMe rear	RAID: PERC 12 & 13 , SWRAID HBA465e , H365i, H965i, H975i Boot: BOSS Flatbread NVMe (Hot-Swap) & M.2 Interposer Front & Rear
Network	Optional 2 x 1GbE LOM, 1 x OCP 3.0	Rear: 1 / 2x x8/16 OCP Cold Aisle: 2x x16 OCP opt. Industry Standard FW
PCIe slots	Up to 3 x PCIe Slots (with up to 2 PCIe Gen5), SNAP I/O option	Rear: Up to 3 x PCIe Slots Gen5 Cold Aisle: 2x x16 FHHL Gen5
Accelerators	3x SW GPU and DPU	3x SW GPU and DPU
Integrated Ports	Front: iDRACdirect USB type-C, KVM (DP & USB type-A), Quicksync opt. Rear: USB type-A, VGA, mgt. network RJ45	Front: iDRACdirect USB type-C, KVM opt. (DP & USB type-A) Cold Aisle: 1x mgt. network RJ45, DB9 Rear: USB type-A, VGA, mgt. network RJ45
System Mgmt	iDRAC9 Express, Enterprise, Datacenter, and OME	iDRAC10 Express, Enterprise, Datacenter and OME
PSU	AC (Platinum): 800W, 1400W AC (Titanium): 700W, 1100W, 1800W LVDC @-48VDC Input: 1100W	AC (Platinum): 800W, 1100W AC (Titanium): 800W , 1100W, 1500W , 1800W 277VAC & HVDC (Titanium): 1500W -48VDC NAF: 1400W
Dimensions	2U H x W x D: 86.8mm x 482mm x 758mm (without bezel)	2U H x W x D: 86.8mm x 482mm x 814mm (without bezel)
Country SiL	Tier 1, 2, and 3	Tier 1, 2, and 3

Dell PowerEdge R570

One Socket Optimized 2U

- Powered by Next-Gen Intel Processors: **Sierra Forest** (330W TDP), Granite Rapids SP & **RIO** (350W TDP) - 1 socket
- Up to **144 Cores**
- Up to 16 x DDR5 RDIMMs - **4TB max***
- Up to **6400 MT/s DDR5**
- **24Gb DRAM support****



Flexible I/O

- Up to **4 x FHHL** PCIe Gen5 slots + DW GPU
- **Up to 2x** OCP 3.0 slots (front & rear)
- Enhanced Industry Firmware portfolio (NIC & NVMe)

System Management

- iDRAC10

Cold Aisle Support **NEW**

- Easily serviceable from the cold aisle, improving datacenter engineers' working environment
 - **2xPCIe FH/2xOCP & rear accelerator + 8/16xE3 NVMe**
 - **Front VGA, Serial, BOSS, iDRACdirect, mgt LAN**

Flexible Storage

- 12 x 3.5" SAS/SATA HDD/SSD + opt. 4xE3 rear NVMe
- 8 x 2.5" SAS/SATA/U.2 & 16/24 x 2.5" SAS/SATA
- **16/32 x E3 NVMe**
- BOSS & **M.2** Boot options, PERC 12

Gen-to-Gen: R570 Series

Improvements over 16th Gen

Feature	R760xs	R760	HS5620	R570
CPU	Up to 2x Sapphire Rapids or Emerald Rapids up to 250W; up to 32 cores Air-Cooled	Up to two 4th Generation Intel® Xeon® Scalable processors with up to 56 cores per processor Support for up to 2 x 350W processors Direct Liquid Cooling support	2x Sapphire Rapids (SPR) CPUs (S4/G5/G6) Support up to 225W TDP Up to 250W TDP with HW config restriction (support 270W SS SKUs)	1x Sierra Forest, Granite Rapids, Granite Rapids R1S, Clearwater Forest Support up to 350W TDP
Memory	Up to 16x DDR5 5200 MT/s (up to 1.5TB max)	Up to 32 x DDR5 RDIMMs DIMM Speed: Up to 4800 MT/s	Up to 16x DDR5 4800 MT/s RDIMMs (2TB max) 8 channel, 1 DIMMs/channel 16 / 32 / 64 / 128 GB/RDIMM standard RAS Optane Memory: No NVDIMM: No	Up to 16x DDR5-6400 MT/s RDIMM (4TB max) 8 channel, 2 DIMMs/channel 16 / 32 / 64 / 128 / 256 GB/RDIMM standard RAS 9x4 memory support (UI) CXL memory support (UI)
Storage	Up to 12x3.5" Up to 16x2.5" Up to 16x2.5"+8x 2.5" NVMe Rear: 2 x 2.5" SAS/SATA HDD/SSD/NVMe Rear BOSS-N1 (2xM.2 NVMe)	Up to 12 x 3.5" SAS/SATA HDD Up to 24 x 2.5" SAS/SATA HDD/SSD or NVMe SSD w/ universal slots Up to 16 x 2.5" SAS/SATA HDD/SSD + 8 x 2.5" NVMe SSD Up to 16 x E3.S NVMe Gen5 direct attach* Up to 4 x rear 2.5" SAS/SATA HDD/SSD or NVMe SSD Up to 4 x rear E3.S NVMe Gen5* Rear BOSS-N1 (2xM.2 NVMe)	Front: Up to 12x 3.5" SAS/SATA HDD + 2x 2.5" SAS3/SATA or NVMe (Gen 4) SSD (Rear) Up to 8x 2.5" NVMe (Gen 4) SSD Up to 16x 2.5" SAS3/SATA SSD + 8x 2.5" NVMe (Gen4) SSD Internal: USB (optional) and monolithic BOSS-N1 (2x M.2), hot swap Support for Channel Firmware devices	Front: 8x2.5" SAS/SATA ; 8x2.5" SAS/SATA/NVMe 8xU.2 & 8xU.2 RAID 12x3.5" SAS/SATA + 4x E3.S NVME (rear) 16x2.5" SAS/SATA RAID ; 24x2.5" SAS/SATA 24x2.5" 16x SAS/SATA + 8x NVMe 32xE3 (rear) Cold Aisle: 8xE3.S NVME & 16xE3.S NVME
Storage Controller	PERC 11; PERC 12 HW SAS4/SATA/NVMe RAID SW RAID: Yes	HW RAID: PERC 11 & 12 (dual PERC option) HW SAS4/SATA/NVMe RAID SW RAID: Yes	HW RAID: PERC 11 (no dual PERC option) PERC 11: HBA355i, H755 SW RAID: Yes	HW RAID: PERC 12 (no dual PERC) HBA465i, H365i, H965i, Boot: BOSS Flatbread NVMe (Hot-Swap) & M.2 Interposer Front & Rear
Network	Embedded 2 x 1 GbE LOM 1x OCP 3.0	Optional 2 x 1GbE LOM, 1 x OCP 3.0	Rear: 2x 1GbE + 1x OCP 3.0 (x8) Support for Channel Firmware devices	Rear: 1 / 2x x16 OCP; Cold Aisle: 2x x16 OCP Channel FW as base
PCIe slots	Up to 6x PCIe Slots, 1x OCP 3.0, 1x PERC; No SNAPI	Up to 8 x PCIe Slots (with up to 4 PCIe Gen5), SNAP I/O option	Up to 6x 16 PCIe I/O slots LP, No SNAPI On-board: 3x LP(x16) Gen4 + 1x LP(x8) Gen4 & R1c: 2x LP(x16) Gen5	Rear: Up to 4x x16 FHHL Gen5 & 3x 16 DWFL Gen5 Cold Aisle: up to 4x 16 FHHL Gen5
Accelerators	Up to 2xSW HH/HL GPU (max 75W)	2 x DW or 6 x SW	None	300W GPU and DPU
Integrated Ports	Front: 1 x USB 2.0, 1 x iDRACDirect (Micro-AB) port, 1 x VGA Rear: 1 x Dedicated iDRACEthernet port, 1 x Serial (optional), 1x USB 2.0, 1x USB 3.0 Internal: 1x USB 3.0 (optional)	Front: 1 x USB 2.0, 1 x iDRACDirect (Micro-AB USB) port, 1 x VGA Rear: 1 x Dedicated iDRACEthernet port, 1 x Serial (optional), 1x USB 2.0, 1 x USB 3.0, 1 x VGA (optional for Liquid Cooling configurations) Internal: 1x USB 3.0 (optional)	Front: 1x USB2.0, 1x iDRACDirect (Micro-USB), 1x VGA, Rear: 1x USB 2.0, 1x USB 3.0, 1x Serial (option), 2x network, 1x iDRACnetwork, 1x VGA	Front: iDRACdirect USB type-C, KVM opt. (DP & USB type-A) Cold Aisle: 1x mgt. network RJ45, DB9 opt Rear: USB type-A, VGA, mgt. network RJ45
System Mgmt	iDRAC9 Express, Enterprise, Datacenter, and OME	iDRAC9 Express, Enterprise, Datacenter and OME	iDRAC9 Express, Enterprise, Datacenter and OME, Open Server Manager (OpenBMC)	iDRAC10 Express, Enterprise, Datacenter and OME
HA	Hot-plug redundant hard drives, PSU, Hot-plug fans. Hot-plug BOSS	Hot-plug redundant hard drives, PSU, Hot-plug fans. Hot-plug BOSS	Hot plug hard drives, PSU, fans, and BOSS.	Hot plug hard drives, PSU, and BOSS. Cold plug fans w/ optional hot-plug
PSU	600W, 700W, 800W, 1100W, 1400W, 1800W	800W, 1400W, 2400W, 700W, 1100W, 1800W, 2800W	700W, 800W, 1100W, 1400W, 1800W	800W, 1100W, 1500W, DC (UI)
Dimensions	H x W x D: 42.8mm x 482mm x 713mm (without bezel)	H x W x D: 86.8mm x 482mm x 758mm (without bezel)	H x W x D: 2U x 434mm x 721mm	2U M- FLW
Country Sil	Tier 1, 2, and 3	Tier 1, 2, and 3	Tier 1, 2, and 3	Tier 1, 2, and 3

Dell PowerEdge R470

Optimized for Cloud Service Providers

- Powered by Next-Gen Intel Processors: **Sierra Forest 6700E** (330W TDP), Granite Rapids SP & **RIO 6500/6700P** (350W TDP) - 1 socket
- Up to **144 Cores**
- Up to 16 x DDR5 RDIMMs - **4TB** max*
- Up to **6400 MT/s DDR5**
- **24Gb DRAM support****

Flexible I/O

- Up to **2 x FHHL/LP** PCIe Gen5 slots
- **Up to 2x OCP 3.0** slots (front & rear)
- **Industry Standard Firmware for COMMs** (NIC & NVMe)



Flexible Storage

- 4 x 3.5" SAS/SATA HDD/SSD + opt. 2 x E3" rear NVMe
- 8 x 2.5" SAS/SATA or NVMe U.2
- 10 x 2.5" SAS/SATA + 4 Universal
- **8/16 x E3 NVMe**
- BOSS & **M.2** Boot options, PERC 12

Cold Aisle Support

- Easily serviceable from the cold aisle, improving datacenter engineers' working environment
 - **2xOCP or 2xPCIe FH & rear accelerators + 8xE3**
 - **Front VGA, Serial, BOSS, iDRACdirect, mgt LAN**

System Management

- iDRAC
- OpenManage Enterprise
- Additional Management frameworks :
 - Dell AIOps
 - NativeEdge

***SRF 1TB per CPU, GNR 4TB per CPU**

**** Available with GNR**

Gen-to-Gen: R470 Series

G2G Changes – compared to HS5610

Feature	R450	R6X0 XS	R6X0	HS5610	R470
CPU	Up to two 3rd Generation Intel Xeon Scalable processors, with up to 24 cores per processor	Sapphire Rapids (Bronze, Silver, Gold5, Gold6) up to 250W; up to 32 cores	Up to two 4th Generation Intel® Xeon® Scalable processors with up to 56 cores per processor Support for up to 2 x 350W processors Direct Liquid Cooling support	2x Sapphire Rapids (SPR) CPUs (S4/G5/G6) Support up to 225W TDP Up to 250W TDP with HW config restriction (support for 270W SS SKUs)	1x Sierra Forest, Granite Rapids, Granite Rapids R1S, Clearwater Forest Support up to 350W TDP
Memory	Memory 16 DDR4 DIMM slots, supports RDIMM max 1 TB, speeds up to 2933 MT/s	16x DDR5 4800 MT/s (up to 1TB max)	Up to 32 x DDR5 RDIMMs DIMM Speed: Up to 4800 MT/s	Up to 16x DDR5 4800 MT/s RDIMMs (2TB max) 8 channel, 1 DIMMs/channel 16 / 32 / 64 / 128 GB/RDIMM standard RAS Optane Memory: No NVDIMM: No	Up to 16x DDR5-6400 MT/s RDIMM (4TB max) 8 channel, 2 DIMMs/channel 16 / 32 / 64 / 128 / 256 GB/RDIMM standard RAS 9x4 memory support (UI)
Storage	Front bays: • Up to 4 x 3.5-inch SAS/SATA (HDD/SSD) max 64 TB • Up to 8 x 2.5-inch SAS/SATA (HDD/SSD) max 61.4 TB	Front: 4x 3.5" SAS / SATA / ChipSATA 8x 2.5" SAS / SATA 10x2.5" SAS / SATA / NVMe Rear: 2 x 2.5" SAS/SATA HDD/SSD/NVMe; Optional Internal NVMe BOSS	Up to 10 x 2.5" SAS/SATA HDD/SSD; or NVMe SSD Up to 16 x E3.S NVMe Gen5 DUAL PERC Up to 14 x E3.S NVMe Gen5 direct attach Up to 2 x 2.5" (rear) SAS/SATA HDD/SSD; or NVMe SSD Up to 2 x E3.S(rear) NVMe Gen5 Rear BOSS-N1 (2xM.2 NVMe) for boot Internal: USB; Bandwidth: SAS4-24Gb, SAS3-12Gb, SATA-6Gb	Front: Up to 4x 3.5" SAS/SATA/ChipSATA HDD + 2x 2.5" SAS3/SATA SSD (Rear) Up to 10x 2.5" SAS3/SATA or NVMe (Gen 4) SSD Cold Aisle (CA): Up to 6x 2.5" NVMe (Gen 4) SSD Internal: USB (optional) and modular BOSS-N1 (2x M.2), non-hot swap CA: Front plug monolithic BOSS-N1 (2x M.2), hot swap Support for Channel Firmware devices	Front: 16X E.3 (Rear) 4x 3.5" SAS/SATA + 2x Rear E3.S 8x 16 E3.S NVMe 8x 2.5" SAS/SATA 8x U.2 & 8x U.2 RAID 10x 2.5" SAS/SATA + 4x Universal Cold Aisle: 8 E3.S NVMe
Storage Controller	Internal controllers (RAID): PERC H345, PERC H355, HBA355i, PERC H745, PERC H755, S150 • Internal Boot: Internal Dual SD Module or Boot Optimized Storage Subsystem (BOSS-S1): HWRAID 2x M.2 SSDs or USB • External PERC (RAID): PERC H840 • External HBA (non-RAID) HBA355e	PERC 11; PERC 12	HW RAID: PERC 11 & 12 (dual PERC option) HW SAS4/SATA/NVMe RAID SW RAID: Yes	HW RAID: PERC 11 (no dual PERC option) PERC 11: HBA355i, H755 Chipset SATA/SW RAID: Yes	HW RAID: PERC 12 (no dual PERC) HBA465i, H365i, H965i, Boot: BOSS Flatbread NVMe (Hot-Swap) & M.2 Interposer Front & Rear
Network	2 x 1 GbE LOM; 1 x OCP 3.0	2 x 1 GbE LOM; 1 x OCP 3.0	Optional 2 x 1GbE LOM, 1 x OCP 3.0	Rear: 2x 1GbE + 1x OCP 3.0 (x8) Cold-Aisle: 2x OCP 3.0 (FLOP) Support for Channel Firmware devices	Rear: 1 / 2x 16 OCP (gen5) Cold Aisle: 2x 16 OCP opt Channel Firmware as base
PCIe slots	2 x PCIe Gen4 slots + PCIe Gen • 2 x16 Gen4 (x16 connector) low profile, half length • 1 x4 Gen3 (x8 connector) low profile, half length	• 1 CPU Configuration: Up to 2 PCIe slots (1 x16 Gen4 + 1 x8 Gen5) • 2 CPU configuration: Up to 3 PCIe Gen4 slots (1 x16 Gen4 + 2 x8 Gen4) or up to 2 PCIe Gen5 slots (1 x16 Gen5 + 1 x8 Gen5)	Up to 3 x PCIe Slots (with up to 2 PCIe Gen5), SNAP I/O option	Up to 2x PCIe I/O slots LP, No SNAPI support R1a: 1x LP(x16) Gen4 R1b: 1x LP(x8) Gen5 R2c: 1x LP(x16) Gen4 R2e: 1x LP(x16) Gen5	Rear: Up to 2x 16 FHHL Gen5 Cold Aisle: 2x x16 FHHL Gen5

PowerEdge R360

Single Socket Rack

- Single Raptor Lake CPU(6300 series or E-2400 series) with up to 8C
- 4 x DDR5 DIMMs per node at 4400 MT/s

Flexible I/O

- 2 x PCIe Gen 4 or 2 x PCIe Gen 5
- BOSS-N1 (2 x M.2 NVMe) for boot



Filter Bezel

- Dust/grease proof filter bezel is ideal for restaurant retailer and dust-heavy workspace

Support for up to 8 drives

- Up to 4 x 3.5" SATA/SAS HDD/SSD
- Up to 8 x 2.5" SATA/SAS HDD/SSD

GPU Support

- Support NVIDIA A2 GPU for media acceleration and AI workload

System Management

- iDRAC²
- OpenManage Enterprise²
- Additional Management frameworks :
 - Dell AIOps
 - NativeEdge

Technical Specifications – R350, R360

Features	PowerEdge R350	PowerEdge R360
CPU	Single Socket Intel® Xeon® E-2300 Processor (Rocket Lake-E) with up to 8 cores Xeon and Pentium	Single Socket Intel® Xeon® 6300 series processor(Raptor Lake-E Refresh) or E-2400 series Processor (Raptor Lake-E) with up to 8 cores or Intel® Pentium® processor with 2 cores
Memory	DDR4: Up to 4 x DDR4 UDIMMs (Max 128G) DIMM Speed: Up to 3200 MT/s	DDR5: Up to 4 x DDR5 UDIMMs (Max Capacity 128G) DIMM Speed: Up to 4400 MT/s
Storage (Chassis options)	Up to 4 x 3.5" – 12Gb SAS, 6Gb SATA Up to 8 x 2.5" – 12Gb SAS, 6Gb SATA Hot plug BOSS-S2	Up to 4 x 3.5" – 12Gb SAS, 6Gb SATA Up to 8 x 2.5" – 12Gb SAS, 6Gb SATA Hot plug BOSS-N1
PCIe slots	2 x PCIe Gen 4 slots	2 x PCIe Gen 4 slots
Storage Controller	HW RAID: PERC 10.5, PERC 11 Chipset SATA/SW RAID: Yes	HW RAID: PERC 11 Chipset SATA/SW RAID: Yes
Network	2 x 1GbE LOM	2 x 1GbE LOM
Bezel	Optional LCD Bezel or Security Bezel	Security Bezel or optional Filter Bezel
GPU	Not supported. T4 capable	Support entry GPU (1 x NVIDIA A2)
Integrated Ports	Front: 1 port (USB 2.0), 1 (micro-USB, iDRAC Direct) Rear: 1 port (USB 3.0) + 1 port (USB 2.0)+1 x VGA Internal: 1 port (USB 2.0)	Front: 1 port (USB 2.0), 1 (micro-AB USB, iDRAC Direct) Rear: 1 port (USB 3.0) + 1 port (USB 2.0) + 1 x VGA Internal: 1 port (USB 3.2)
System Management	iDRAC9 with Lifecycle Controller; Express, Enterprise, Datacenter, and OME Advanced Features	iDRAC9 with Lifecycle Controller; Express, Enterprise, Datacenter, and OME Advanced Features
High Availability	Hot Plug/RAID controlled drives, Fans, PSUs, BOSS (2 x M.2)	Hot Plug/RAID controlled drives, Fans, PSUs, BOSS-N1 (2 x M.2 NVMe) for boot
Power Supplies	600W Platinum	600W Platinum, 700W Titanium
Dimensions	H x W x D: 1U x 482mm x 534.59 mm	H x W x D: 1U x 482mm x 563.3 mm
Form Factor	1U Rack Server	1U Rack Server

PowerEdge R260

Single Socket Rack

- Single Raptor Lake CPU(6300 series or E-2400 series) with up to 8C
- 4 x DDR5 DIMMs per node at 4400 MT/s



Flexible I/O

- Up to 2 x PCIe Slots Gen4 on Riser
- BOSS-N1 (2 x M.2 NVMe) for boot

Shorter Depth

- 17-inch depth

Support for up to 6 drives

- Up to 2 x 3.5" SATA/SAS HDD/SSD(SW RAID, HW RAID)
- Up to 6 x 2.5" SATA/SAS HDD/SSD(HW RAID)
- Up to 6 x 2.5" SATA/SAS HDD/SSD(SW RAID)

Filter Bezel

- Dust/grease proof filter bezel is ideal for restaurant retailer and dust-heavy workspace

System Management

- iDRAC
- OpenManage Enterprise
- Additional Management frameworks :
 - Dell AIOps
 - NativeEdge

Technical Specifications – R250, R260

Features	PowerEdge R250	PowerEdge R260
CPU	Single Socket Intel® Xeon® E-2300 Processor (Rocket Lake-E) with up to 8 cores Xeon and Pentium	Single Socket Intel® Xeon® 6300 series processor(Raptor Lake-E Refresh) or E-2400 series Processor (Raptor Lake-E) with up to 8 cores or Intel® Pentium® processor with 2 cores
Memory	DDR4: Up to 4 x DDR4 UDIMMs (Max Capacity 128G) DIMM Speed: Up to 3200 MT/s	DDR5: Up to 4 x DDR5 UDIMMs (Max Capacity 128G) DIMM Speed: Up to 4400 MT/s
Storage (Chassis options)	Up to 4x 3.5" SATA/SAS HDD/SSD Up to 4 x 2.5" SATA/SAS HDD/SSD BOSS-S1	Up to 2 x3.5" SATA/SAS HDD Up to 6 x2.5" SATA/SAS HDD/SSD Hot plug BOSS-N1
PCIe slots	2 x PCIe Gen 4 slots	2 x PCIe Gen 4 slots
Storage Controller	HW RAID: PERC 11 Chipset SATA/SW RAID: Yes	HW RAID: PERC 11 Chipset SATA/SW RAID: Yes
Network	2 x 1GbE LOM	2 x 1GbE LOM
Bezel	Security Bezel	Security Bezel or optional Filter Bezel
GPU	Not supported	Not supported
Integrated Ports	Front: 1 port (USB 2.0), 1 (micro-USB, iDRAC Direct) Rear: 1 port (USB 3.0) +1 port (USB 2.0)+1 x VGA Internal: 1 port (USB 3.0) (optional)	Front: 1 port (USB 2.0), 1 iDRAC Direct (micro-AB USB) port Rear: 1 port (USB 3.2) +1 port (USB 2.0)+1 x VGA Internal: 1 port (USB 3.2)
System Management	iDRAC9 with Lifecycle Controller; Express, Enterprise, Datacenter, and OME Advanced Features	iDRAC9 with Lifecycle Controller; Express, Enterprise, Datacenter, and OME Advanced Features
Power Supplies	450W cable Bronze, 450W cable Platinum, 700W Titanium	450W cable Platinum, 700W Titanium
Dimensions	H x W x D: 42.8mm (1.68 in) x 482mm (18.97 in) x 585 mm (23.06 in)	H x W x D: 42.8mm (1.68 in) x 482mm (18.97 in) x 426.6 mm (16.8 in) (with cable PSU and without bezel)
Form Factor	1U Rack Server	1U Rack Server

PowerEdge T-Series Family

T-SERIES

Flexible, quiet, and cost-effective

Adapt to changing workloads with flexible expansion options

Strong, modern IT infrastructure

High performance and greater GPU capacity



Secure remote monitoring and lifecycle management



Up to **2x** Performance boost¹



Up to **50%** Better data storage²



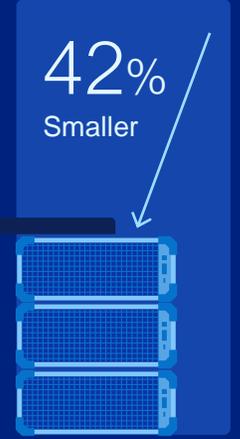
Flexible, seamless expansion

Compact size for desks, offices, or non-traditional IT spaces

Up to **23%** Greater performance per watt



42% Smaller



Stackable



Office-friendly operations

Ideal for professional environments without a dedicated server room



Filtered bezels eliminate dust and grease



Minimal operating noise



Designed for office environments



¹Based on November 2023 Dell labs testing subjecting the PowerEdge T350 and T360 tower servers to a PostgreSQL benchmark with scaling factor 1000, 1000 clients, and both read and write operations. Results were obtained via a Phoronix test suite. Similar results can be expected comparing the PowerEdge R360 and R350 with the same system configurations.

²Based on November 2023 Dell labs testing subjecting the PowerEdge T350 and T360 tower servers to an Apache Spark benchmark via a Phoronix test suite. Benchmark results were obtained during a run with 40000000 rows and 1000 Partitions to calculate the Pi benchmark using Dataframe. Actual results will vary. Similar results can be expected comparing the PowerEdge R360 and R350 with the same system configurations.

T-SERIES

PowerEdge T560, T360, T160

Capability	Specification
Processor Options	Intel Xeon E-2400 series (up to 8 cores) to 5th Gen Intel Xeon Scalable (up to 32 cores)
CPU Configurations	Single & Dual CPU Configurations
GPU Support	Support for DW & SW GPUs
Memory	Up to 16 DDR5 DIMMS
I/O Configurations	Front/Rear options
Storage Interface	SAS, SATA, NVMe
Management & Security	iDRAC9 with OpenManage Suite
Form Factor	3U to 4.5U Tower Configurations
Cooling Options	Air Cooling



Ideal for:

- Collaboration
 - Real-time database management
 - Virtualization
- Near-edge applications
 - AI/ML inferencing
 - Data analytics



T560



T360



T160

PowerEdge T560

Exceptional Performance

- Powered by up to two 4th Generation Intel® Xeon® Scalable processors with up to 32 cores per processor
- Powered by up to two 5th Generation Intel® Xeon® Scalable processors with up to 28 cores per processor
- Up to 16 x DDR5 RDIMMs (1TB max)

Prepped for data analytics and machine learning

- Up to 2 Double-Wide GPU
- Up to 4 x PCIe Gen 4 slots

System Management

- iDRAC
- OpenManage Enterprise
- Additional Management frameworks :
 - Dell AIOps
 - NativeEdge



Designed for high reliability

- Hot-plug BOSS
- Hot-plug HDD/SSD
- Hot-plug redundant power supplies
- PERC 11 & 12, SW and HW RAID

Expandable I/O and Storage

- Faster I/O throughput: PCIe Gen 5
- Increased memory performance with DDR5 4800MT/s
- Increased maximum storage with up to 12 x 3.5" HDD/SSDs, or 24 x 2.5" SSDs, or 8 x 3.5"/2.5" HDD/SSDs+ 8 x NVMe SSDs

Technical Specifications – T550, T560

Features	PowerEdge T550	PowerEdge T560
CPU	Up to two 3rd Generation Intel® Xeon® Scalable processors with up to 32 cores per processor Support for up to 2 x 220W processors	Up to two 4th Generation Intel® Xeon® Scalable processors with up to 32 cores per processor Up to two 5th Generation Intel® Xeon® Scalable processors with up to 28 cores per processor
Memory	DDR4: Up to 16 x RDIMM (1TB) DIMM Speed: Up to 3200 MT/s	Up to 16 DDR5 RDIMMs (1TB Max) DIMM Speed: Up to 5200MT/s
Storage (Chassis options)	Up to 8 x 3.5" Hot Plug SATA/SAS HDDs/SSDs Up to 24 x 2.5" Hot Plug SAS/SATA HDDs/SSDs Up to 8 x 3.5" Hot Plug SATA/SASHDDs/SSDs and 8 x NVMe SSDs Optional: TBU in 5.25" bay BOSS-S1 (2 x M.2) for boot Bandwidth: SAS-12Gb, SATA-6Gb	Up to 12 x 3.5" Hot Plug SATA/SAS HDD/SSDs Up to 24 x 2.5" Hot Plug SAS/SATA HDD/SSDs Up to 8 x 3.5" Hot Plug SATA/SAS HDD/SSDs and 8 x NVMe SSDs Optional: TBU in 5.25" bay Internal BOSS-N1 (2 x M.2 NVMe) for boot Bandwidth: SAS-24Gb/12Gb, SATA-6Gb
Storage Controller	HW RAID: PERC 11 fPERC 10.5/11, SAS3 & SAS4 Chipset SATA/SW RAID	HW RAID: PERC 11 & 12, SAS3 & SAS4
Network	2 x 1GE + 1 x OCP 3.0	2 x 1GE + 1 x OCP 3.0;
PCIe Slots	Up to 5x PCIe Gen 4 slots (all x16) + 1 x PCIe Gen 3 (x8)	3 x16 FH, 1 x8 FH Gen 4 slots and 2 x16 Gen 5 DW slots
GPU	Up to 2 x DW	Up to 2 x DW
Integrated Ports	Front: 2 ports (USB 3.0+USB 2.0), 1 iDRACDirect micro-USB Rear: 1 ports (USB 3.0), 1 ports (USB 2.0), serial (option), network, iDRAC9 GE, secondary VGA, SysID	Front: 2 ports (USB 3.0+USB 2.0),, 1 iDRACDirect micro-USB Rear: 1 ports (USB 3.0), 1 ports (USB 2.0), serial (option), network, iDRAC9 GE, secondary VGA, SysID
System Management	iDRAC9 Enterprise, Datacenter license options; OpenManage Enterprise and Plugins (PowerManager, SupportAssist, and Update Manager) iDRACDirect, Quick Sync 2.0	iDRAC9 Enterprise, Datacenter license options; OpenManage Enterprise and Plugins (Power Manager, SupportAssist, and Update Manager). iDRACDirect, Quick Sync 2.0
High Availability	Hot Plug/RAID controlled drives, Fans, PSU	Hot Plug/RAID controlled drives, Fans, PSU
Power Supplies	600W, 800W, -48Vdc-- -60Vdc/1100W, 1400W, 2400W	600W, 700W, 800W, -48Vdc-- -60Vdc/1100W, 1400W, 1800W, 2400W
Dimension	H x W x D: 459mm x 200mm x 660mm	H x W x D: 459mm x 200mm x 660mm
Form Factor	4.5U Tower Server	4.5U Tower Server

PowerEdge T360

Single Socket Tower

- Single Raptor Lake CPU (6300 series or E-2400 series) with up to 8C
- 4 x DDR5 DIMMs per node at 4400 MT/s

Support for up to 8 drives

- Up to 4 x 3.5" SATA HDD/SSD
- Up to 8 x 3.5" SATA/SAS HDD/SSD
- Up to 8 x 2.5" SATA/SAS HDD/SSD



Flexible I/O

- 3 x PCIe Gen 4 + 1 x PCIe Gen 5
- BOSS-N1 (2 x M.2 NVMe) for boot

Filter Bezel

- Dust/grease proof filter bezel is ideal for restaurant retailer and dust-heavy workspace

GPU Support

- Support entry GPU for media acceleration and AI workload

System Management

- iDRAC
- OpenManage Enterprise
- Additional Management frameworks :
 - Dell AI Ops
 - NativeEdge

Technical Specifications – T350, T360

Features	PowerEdge T350	PowerEdge T360
CPU	Single Socket Intel® Xeon® E-2300 Processor (Rocket Lake-E) with up to 8 cores Xeon and Pentium	Single Socket Intel® Xeon® 6300 series processor(Raptor Lake-E Refresh) or E-2400 series Processor (Raptor Lake-E) with up to 8 cores or Intel® Pentium® processor with 2 cores
Memory	DDR4: Up to 4 x DDR4 UDIMMs (Max 128G) DIMM Speed: Up to 3200 MT/s	DDR5: Up to 4 x DDR5 UDIMMs (Max Capacity128G) DIMM Speed: Up to 4400 MT/s
Storage (Chassis options)	Up to 8 x 3.5" – 12Gb SAS, 6Gb SATA Up to 8 x 2.5" – 12Gb SAS, 6Gb SATA Hot plug BOSS-S2	Up to 8 x 3.5" – 12Gb SAS, 6Gb SATA Up to 8 x 2.5" – 12Gb SAS, 6Gb SATA Hot plug BOSS-N1
PCIe slots	2 x PCIe Gen 3 slots+2 x PCIe Gen 4 slots	3 x PCIe Gen 4 slots+1 x PCIe Gen 5 slot
Storage Controller	HW RAID: PERC 10.5, PERC 11 Chipset SATA/SW RAID: Yes	HW RAID: PERC 11 Chipset SATA/SW RAID: Yes
Network	2 x 1GbE LOM	2 x 1GbE LOM
Bezel	Optional LCD Bezel or Security Bezel	Security Bezel or optional Filter Bezel
GPU	Not supported. T4 capable	Support entry GPU (1 x Nvidia A2)
Integrated Ports	Front: 1 port (USB 3.0), 1 (micro-USB, iDRAC Direct) Rear: 1 port (USB 3.0) + 5 port (USB 2.0)+1 x VGA	Front: 1 port (USB 3.2), 1 (micro-USB, iDRAC Direct) Rear: 3 port (USB 3.2) + 3 port (USB 2.0)+ 1 x VGA
System Management	iDRAC9 with Lifecycle Controller; Express, Enterprise, Datacenter, and OME Advanced Features	iDRAC9 with Lifecycle Controller; Express, Enterprise, Datacenter, and OME Advanced Features
High Availability	Hot Plug/RAID controlled drives, Fans, PSUs, BOSS (2 x M.2)	Hot Plug/RAID controlled drives, Fans, PSUs, BOSS-N1 (2 x M.2 NVMe) for boot
Power Supplies	450W Bronze, 600W Platinum	450W Platinum, 600W Platinum, 700W Titanium
Dimensions	H x W x D: 369mm (14.54 in) x 175mm (6.88 in) x 560 mm (22.06 in) (with bezel)	H x W x D: 369mm (14.54 in) x 175mm (6.88 in) x 560 mm (22.06 in) (with bezel)
Form Factor	4.5U Tower Server	4.5U Tower Server

PowerEdge T160

Single Socket Tower

- Single Raptor Lake CPU(6300 series or E-2400 series) with up to 8C
- 4 x DDR5 DIMMs per node at 4400 MT/s

Smaller dimension

- 17L server can go anywhere



Filter Bezel

- Dust/grease proof filter bezel is ideal for restaurant retailer and dust-heavy workspace

Support for up to 5 drives

- Up to 3 x 3.5" SATA HDD/SSD
- Up to 3 x 3.5" SATA/SAS HDD/SSD+2 x 2.5" SATA/SAS SSD

Unpainted Steel

- Unpainted steel with no paint to support the sustainability
- Recycle steel are used to build T160

System Management

- iDRAC
- OpenManage Enterprise
- Additional Management frameworks :
 - Dell AIOps
 - NativeEdge

Technical Specifications – T150, T160

Features	PowerEdge T150	PowerEdge T160
CPU	Single Socket Intel® Xeon® E-2300 Processor (Rocket Lake-E) with up to 8 cores Xeon and Pentium	Single Socket Intel® Xeon® 6300 series processor(Raptor Lake-E Refresh) or E-2400 series Processor (Raptor Lake-E) with up to 8 cores or Intel® Pentium® processor with 2 cores
Memory	DDR4: Up to 4 x DDR4 UDIMMs (Max 128G) DIMM Speed: Up to 3200 MT/s	DDR5: Up to 4 x DDR5 UDIMMs (Max Capacity 128G) DIMM Speed: Up to 4400 MT/s
Storage (Chassis options)	Up to 4x 3.5" SATA/SAS HDD/SSD Up to 4 x 2.5" SATA/SAS HDD/SSD BOSS-S1	Up to 3 x3.5" SATA/SAS HDD/SSD+2 x2.5" SATA/SAS HDD/SSD (Up to 5 x 2.5" in total) Hot plug BOSS-N1
PCIe slots	2 x PCIe Gen 4 slots+ 2 x PCIe Gen 3 slots	2 x PCIe Gen 4 slots
Storage Controller	HW RAID: PERC 11 Chipset SATA/SW RAID: Yes	HW RAID: PERC 11 Chipset SATA/SW RAID: Yes
Network	2 x 1GbE LOM	2 x 1GbE LOM
Bezel	Optional LCD Bezel or Security Bezel	Optional Filter Bezel
GPU	Not supported	Not supported
Integrated Ports	Front: 2 port (USB 3.0), 1 (micro-USB, iDRAC Direct) Rear: 5 port (USB 3.0) +1 port (USB 2.0)+1 x VGA	Front: 1 port (USB 3.0), 1 (micro-USB, iDRAC Direct) Rear: 3 port (USB 3.0) + 3 port (USB 2.0)+ 1 x VGA
System Management	iDRAC9 with Lifecycle Controller; Express, Enterprise, Datacenter, and OME Advanced Features	iDRAC9 with Lifecycle Controller; Express, Enterprise, Datacenter, and OME Advanced Features
Power Supplies	300W cable Bronze, 400W cable Platinum	300W cable Bronze, 500W cable Platinum
Dimensions	H x W x D: 360 mm (14.17 in) x 175 mm (6.88 in) x 453.75 mm (17.86 in) (with bezel) 28L	H x W x D: 329.5 mm (12.97in) x 132.52 mm (5.21in) x 408.8 mm (16.09 in) (with bezel) 17L
Form Factor	4U Tower	3U Tower

PowerEdge M-Series Family

M-SERIES

Performance, Density, and Sustainability without Compromise

Unmatched Compute Density



72

72 nodes per rack



Built for AI, HPC, and tomorrow's most demanding workloads

Easy to deploy and manage

Cold aisle serviceability. Quick disconnects for cable free liquid connectivity. Front I/O cabling.



Seamless management

AI-enabled iDRAC and OpenManage Enterprise ensure smarter, simpler server operations



Uncompromised performance

The latest AMD EPYC 5th Gen CPUs

27K

Up to 27,000 cores per rack



M-Series are available pre-integrated in IR7000 racks—fully validated, tested, and delivered as a ready-to-deploy solution for faster time to value.



Energy efficient

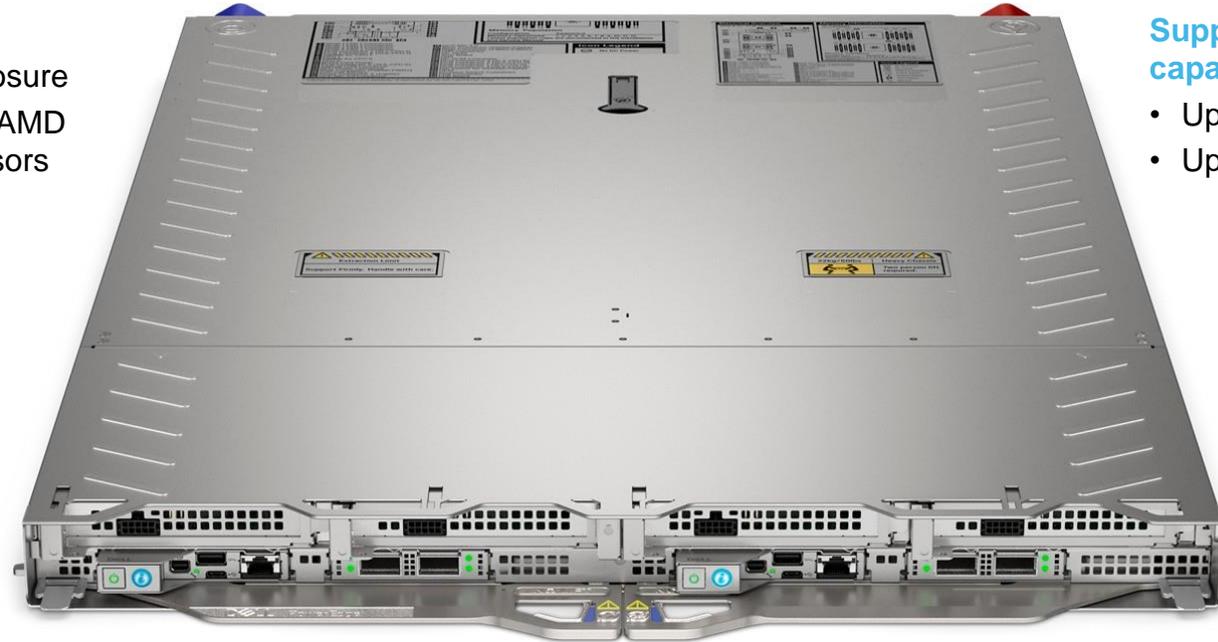
Hybrid cooling with air + liquid for optimized power utilization



PowerEdge M7725

A step ahead in processing

- 2x M7725 nodes in 1OU enclosure
- Each M7725 powered by two AMD EPYC 5th Generation processors



Support for high-speed and memory capacity

- Up to 24 DDR5 DIMMs
- Up to 6400 MT/s (1DPC)

Flexible Storage

- 2x E3.S with 2 x 16 PCIe Gen5 slots, LP
- BOSS with 2x M.2

Ease to deploy & Manage

- Blind-mates to DC Bus Bar & Quick disconnect for DLC
- Hybrid Cooling – liquid to CPUs, air for rest
- Near 100% heat capture for sustainable deployments

Flexible I/O and Cold Aisle Support

- 100% front I/O
- 2 x16 PCIe Gen5 slots, LP or FH
- One OCP NIC 3.0
- 1 x 1GbE LOM

Technical Specifications – M7725

Features

PowerEdge M7725

CPU	Two 5th Generation AMD EPYC 9005 Series processors with up to 128 Zen5 cores or 192 Zen5c cores per node		
Memory	24 DDR5 DIMM slots per node, speeds up to 6400 MT/s Supports registered ECC DDR5 DIMMs only		
Front Drive Bays	2 x EDSFF E3.S Gen5 NVMe SSDs per node and 4 per system		
Storage Controller	Internal boot: Boot Optimized Storage Subsystem (BOSS-N1 Modular DC-MHS): 2 x M.2 SSDs		
Integrated Rack Solution	IR7000 ORv3 (OCP Open Rack version 3)		
Chassis	M7701 chassis supports 2 x M7725 nodes		
Sleds	Each M7725 supports 2 AMD EPYC 9005 processors per node and 4 processors per system		
Form Factor	IR7000 = 44 OU (Open Rack Units) M7701 is 1OU, M7725 is node Note: 1 OU = 48 mm (1.88 inch) height, and 538.98 mm (21.22 inch) width.		
Cooling	Direct Liquid Cooling (DLC) for CPUs Air cooling for all other components		
Power Supplies	<ul style="list-style-type: none">IR7000 rack consists of power shelf 33kW that supports 6 x 5500 W AC PSUsThe power shelf supplies up to 50 VDC to the M7725 through Power bus bar located on IR7000 rack		
Dimensions and Weight	<table><tr><td>IR7000<ul style="list-style-type: none">Height — 2286 mm (90 inches)Width — 750 mm (29.52 inches)Depth — 1200 mm (47.24 inches) — 1340 mm (57.75 inches) with front and rear doors</td><td>M7725 nodes installed M7701 chassis<ul style="list-style-type: none">Height — 46.45 mm (1.83 inches)Width — 537.0 mm (21.14inches) no bezel supportDepth — 848.80 mm(33.41 inches) Hook to IMM moduleWeight — 26.65 kg (58.75 pounds)</td></tr></table>	IR7000 <ul style="list-style-type: none">Height — 2286 mm (90 inches)Width — 750 mm (29.52 inches)Depth — 1200 mm (47.24 inches) — 1340 mm (57.75 inches) with front and rear doors	M7725 nodes installed M7701 chassis <ul style="list-style-type: none">Height — 46.45 mm (1.83 inches)Width — 537.0 mm (21.14inches) no bezel supportDepth — 848.80 mm(33.41 inches) Hook to IMM moduleWeight — 26.65 kg (58.75 pounds)
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Network	1x OCP 3.0 slot in the front of each node		
PCIe slots	Up to 2 x16 Gen5 PCIe slots per node		
DPU	1x BF3 1x400GbE per node or 1x BF3 2x 200GbE per node		
Ports	<table><tr><td>Front ports<ul style="list-style-type: none">1 x USB 2.0 Type - A port1 x USB 2.0 Type - C port1 x RJ45 dedicated iDRAC Ethernet port1 x Mini-DisplayPortNote: All front ports are located on the DC-SCM module</td><td>Internal ports<ul style="list-style-type: none">1 x USB 3.1 Type A port</td></tr></table>	Front ports <ul style="list-style-type: none">1 x USB 2.0 Type - A port1 x USB 2.0 Type - C port1 x RJ45 dedicated iDRAC Ethernet port1 x Mini-DisplayPort Note: All front ports are located on the DC-SCM module	Internal ports <ul style="list-style-type: none">1 x USB 3.1 Type A port
Front ports <ul style="list-style-type: none">1 x USB 2.0 Type - A port1 x USB 2.0 Type - C port1 x RJ45 dedicated iDRAC Ethernet port1 x Mini-DisplayPort Note: All front ports are located on the DC-SCM module	Internal ports <ul style="list-style-type: none">1 x USB 3.1 Type A port		
System Management	iDRAC10, iDRAC Direct, iDRAC RESTful API with Redfish, iDRAC Service Module		
Operating Systems	Ubuntu, RHEL, SUSE		

PowerEdge Edge XR Family

Built for the extreme edge

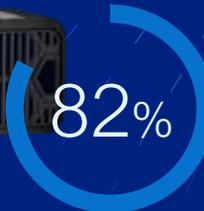
High-performance and durability in any environment

Accelerate advanced workloads

Scalable high-performance optimized with GPU capabilities



AI and visualization ready



82% of Fortune 100 use Dell Technologies for their edge solutions¹



Enhanced durability

Resilient against shock, vibration, dust, and extreme thermal environments



Monitored filtered bezels



All-weather reliability

Up to +65°C
As low as -20°C²



MIL/NEBS certified



Design simplicity and versatility

Make efficient use of your space with servers that maximize compute power per rack unit



Secure remote monitoring and lifecycle management



Compact short-depth fits perfectly in tight spaces



Front-facing I/O makes servicing quick and easy

¹ Dell Technologies analysis of US Fortune 500, July 2023.
² XR8000 support an operating temperature range of -20 to 65°C

For compute outside the data center

PowerEdge XR4000 & XR8000

Capability	Specification
Architecture	Sled-based
Chassis	Short depth: <19 in
Processor Options	Intel® Xeon® Scalable processors (4th and 5th Gen) with up to 32 cores
GPU Support	Support for DW & SW GPUs
Memory	DDR5 DIMM slots with ECC support
I/O Configurations	Front options
Storage Interface	NVMe SSD
Management & Security	iDRAC9 with OpenManage Suite
Form Factor	1U & 2U Rack Configurations
Cooling Options	Air Cooling
Sustainability	Designed with energy efficiency and recyclability in mind



PowerEdge XR5 & XR7

Capability	Specification
Architecture	Compact rack server
Chassis	Short depth: <19 in
Processor Options	Intel® Xeon® Scalable processors (4th and 5th Gen) with up to 32 cores
GPU Support	Support for DW & SW GPUs
Memory	DDR5 DIMM slots with ECC support
I/O Configurations	Front/Rear options
Storage Interface	Support for SAS, SATA, and NVMe SSDs
Management & Security	iDRAC9 with OpenManage Suite
Form Factor	1U & 2U Rack Configurations
Cooling Options	Air Cooling with cold swap fans
Sustainability	Designed with energy efficiency and recyclability in mind



Ideal for:

- Virtualization Desktop
- Infrastructure (VDI)
- Virtual Machines
- Video surveillance
- vSAN/VM
- Point of sale
- Data communication
- Centralized RAN
- Distributed RAN
- Network Edge
- Manufacturing
- Retail
- Military & Defense

Idea for:

- Telco/5G, vRAN, ORAN
- Retail and Manufacturing
- Video Monitoring
- IoT Device Aggregation
- Military and Defense
- Industrial automation
- Video analytics
- Point of sale analytics
- AI inferencing
- Edge point device aggregation



Dell PowerEdge XR8000 (2U sled)

Single socket Intel Xeon per node

- 4th Generation Intel® Xeon® Scalable processors with optional vRAN boost up 32 cores

Broad range of configurability supporting up to 4 nodes with flexible I/O sled options

- 2U modular front-accessible chassis with dual power supply to support up to 4 nodes
- 2U half-width sled configurations for Edge / Far Edge
- 1U half-width sled configuration for dense compute and network edge optimized work loads



Dual 60 mm PSUs

- -48VDC options: 800W, 1100W, 1400W
- 100 to 240VAC options: 1400W, 1800W

System Management

- iDRAC
- OpenManage Enterprise

Product Family



XR8610

XR8620



XR8000

- Optimized to operate in Class 1 (-20C to 65C) environments
- Short-depth: 430 mm from front I/O wall to rear wall
- Front-accessible and simplified field serviceability

Technical Specifications – XR8000

Features per sled	PowerEdge XR8000
CPU	Intel® Xeon® processors 4th generation SP processors up to 32 cores with optional vRAN Boost
Memory	Up to 8x DDR5 RDIMMs DIMM Speed: 4800 MT/s Up to 64GB per DIMM
GPU Options	Up to 3 x Nvidia 72W L4 GPU
Storage	2x M.2 NVMe No RAID and RAID options Up to 1.92TB, 22110 options
Network	Optional 2 x 25GbE
PCIe slots	XR8620: 2U sled option 2 x FHHL (up to 125W) 1 x FHHL (up to 45W) (Gen5) XR8610: 1U sled option 1x16 FHHL (up to 45W) (Gen5)
Integrated Ports	iDRACdirect via Micro AB USB 1x USB 3.0 / 2.0 Mini DP 2 x RJ45: dedicated BMC and dry input – 7 contacts Micro-USB type B connector for RS232 serial port debugging of OS
System Management	iDRAC9 Enterprise 16th generation
High Availability	Hot plug redundant PSUs
Power Supplies	2x 60mm options: <ul style="list-style-type: none">-48VDC: 700W dual input, 1100W, 1400W100 to 240VAC: 1400W, 1800W
Dimensions	H x W x D: 2U x 434mm x 430mm Up to 50lbs/23kg fully loaded; 2U sled only up to 17lbs/8kg
Form Factor	2U sled-based edge chassis supporting 1U and 2 U half-width sleds
Operating Environment	-20C to 65C
Certs and Tests	NEBS 3 (GR3108 Class 1, GR-1089, GR-63)

Dell PowerEdge XR4000 (2U rackable/stackable sled)

Single Socket 3rd Generation Intel® Xeon® D

- Intel® Xeon® D processor, up to 20C per node
- Up to 4 discrete servers in a single 2U chassis

Support for 2.1-node vSAN

- Embedded NPU running ESXi or Linux
- GPU-ready configurations



System Management

- iDRAC
- OpenManage Enterprise

Intelligent Filtered Bezel

- Secure Locking Bezel
- Filter monitored by iDRAC

Flexible Mounting Options

- Multiple systems securely stack
- VESA bracket compatible
- DIN Rail adapter option

Product Family



XR4000r



XR4000z



XR4000w
(witness node)



XR4510c
(compute sled)



XR4520c
(compute sled)

- -5C to 55C operating temperature
- Short-depth: 350mm from ear-to-rack
- Front and Rear I/O options for simplified field serviceability

Technical Specifications – XR4000

Features

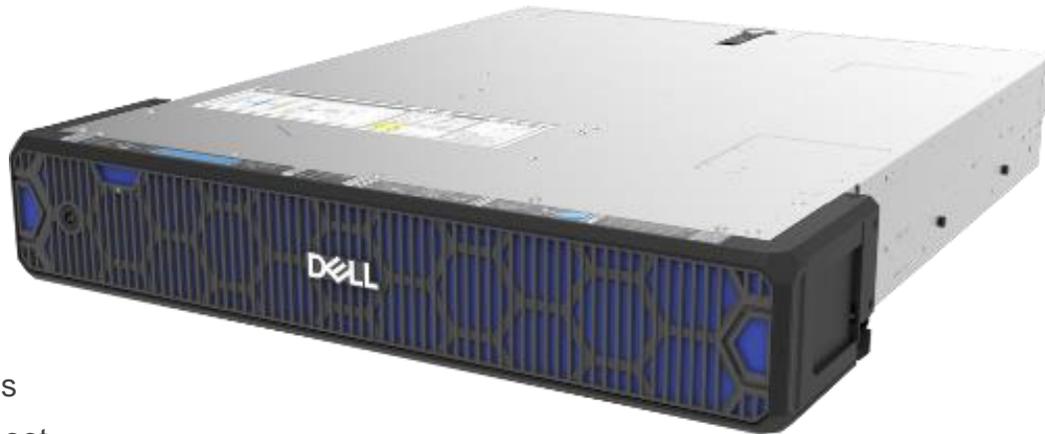
PowerEdge XR4000

CPU	3 rd Generation Intel® Xeon® D processors Up to 20 cores at 120W
Memory	Up to 4 x DDR4 RDIMMs/LRDIMMs DIMM Speed: Up to 3200 MT/s Minimum 1DPC per channel
Storage (Chassis options)	4 x M.2 NVMe (1U) 12 x M.2 NVMe (2U) Up to 3.84TB capacity Read Intensive SSD drives (for general storage use) 800GB capacity Mixed Use SSD drives (for vSAN cache)
Storage Controller	BOSS-N-1 (2 xM.2 NVMe)
Network	4 x 10GbE or 4 x 25 GbE LOM
PCIe slots	2 slots x16 PCIe Gen 4; up to 240W
GPU	2 x 300W (DW) or 4 x 150W (SW)
Integrated Ports	iDRACrj45 & Micro USB 2 x USB Mini DP
System Management	iDRACEnterprise, Datacenter license options; OpenManage Enterprise and Plugins (Power Manager, SupportAssist, and Update Manager). iDRACDirect
High Availability	Hot plug redundant PSUs
Power Supplies	2 x 60mm – 1400W MM AC (110v & 220v) or 1100W -48vDC
Dimensions	H x W x D: 2U x 434mm x 355mm (2U x 267mm x 355mm)
Form Factor	2U Rack Server
Operating Environments	-5C to 55C (restricted configs)
Certs and Tests	MIL-STD (810H, 461G, 901E, 1474E) and NEBS 3 (GR3108 Class 1, GR-1089, GR-63)

Dell PowerEdge XR7620 (2U)

2 Socket Capable

- Two 4th Generation Intel® Xeon® Scalable processors with up to 32 cores per processor



Support for up to 8 drives

- Up to 8x NVMe drives
- BOSS (2 x M.2) for boot
- HW NVMe RAID

Support for latest memory and acceleration

- Up to 16 DDR5 DIMMs @ 4800MTs, 1DPC
- 2 x DW accelerators (up to 300W each)

Flexible I/O

- Front and rear-facing I/O
- Up to 4 x PCIe Gen4/5 slots
- OCP 3.0 for network cards
- 1 x LP slot

System Management

- iDRAC
- OpenManage Enterprise

- -5C to 55C operating temperature
- Up to 2 x DW accelerators (2 x 300W)
- Short-depth 472mm Chassis

Technical Specifications – XR2, XE2420, XR7620

Features	Dell XR2 (1U)	PowerEdge XE2420 (2U)	PowerEdge XR7620 (2U)
CPU	Up to two 2 nd Generation Intel® Xeon® Scalable processors with up to 28 cores per processor	Up to two 2 nd Generation Intel® Xeon® Scalable processors with up to 28 cores per processor Up to 2 x 150W processors	2x 4th Generation Intel® Xeon® Scalable processors with up to 32 cores per processor 2 x 225W processors MCC Focused
Memory	16 x DDR4 RDIMM/LRDIMM 2DPC Unbalanced	16 x DDR4 RDIMM/LRDIMM 2DPC Unbalanced	Up to 16 x DDR5 RDIMMs DIMM Speed: Up to 4800 MT/s 1 DIMM per channel
Storage	4 x U.2 NVMe (Direct attach)	2 x U.2 NVMe \ SATA 4 x U.2 NVMe \ SATA \ SAS (Perc Raid) 6 x EDSFF E1.long	4 x 2.5" univ. backplane NVME direct attach (No SATA\SAS) 4 x 2.5" univ. backplane with fPERC11. SATA\SAS RAID, direct attach U.2 NVME 8 x E3.thin.short, direct attach 8 x E3.thin.short. PERC12
Storage Controller	PERC 9: H330, HBA3330 H730 BOSS available	PERC 9: H330, HBA3330 H730P, H740P	PERC 11: H355, HBA355i, & H755 front PERC 12: H965i front (EDSFF only) BOSS available
Network	2 x 1GbE + OCP 2.0 x8	2 x 1GbE + OCP 2.0 x8	2 x 1GbE LOM + 1 x OCP 3.0 x8 (gen 4)
PCIe slots	2 Slots: 2 x16 PCIe Gen 3	3 Slots: (2) x16 Gen 3; (1) x8 Gen 3	5 slots: (4) x16 (gen 4/5); (1) x16 LP (gen 4)
GPU	1 x 75W (LP)	2 x 300W (DW) or 4 x 75W (SW)	2 x 300W (DW) or 4 x 150W (SW)
Integrated Ports	2 x Rear USB, 2 x Front USB, 1 x (ear) iDRACDirect micro-USB	2 x front USB, 1 x iDRACDirect micro-USB	NAF: 2 x Rear USB, 1 x Front USB, 1 x (ear) iDRACDirect micro-USB RAF: 3 x Front USB, 1 x (ear) iDRACDirect micro-USB
System Management	iDRAC9 Enterprise 14G	iDRAC9 Enterprise 14G	iDRAC9 Enterprise 16th generation
High Availability	Hot plug drives, redundant fans, hot plug redundant PSU, BOSS dual drive for boot (not hot plug)	Hot plug drives, redundant fans, hot plug redundant PSU, BOSS dual drive for boot (not hot plug)	Hot plug drives, redundant fans, hot plug redundant PSU
Power Supplies	2 x 86mm 550W AC or 2 x 600W -48V	2 x 86mm 2400W RAF	2 x 60mm – 800W, 1100W AC\DC, 1400W AC/DC, 1800W
Dimensions	H x W x D: 2U x 434mm x 514mm	H x W x D: 2U x 434mm x 411mm	H x W x D: 2U x 482.6mm x 471.8mm
Form Factor	1U Rack Server	2U Rack Server	2U Rack Server
Thermals	5C to 45C (restricted configs)	5C to 45C (restricted configs)	-5C to 55C (restricted configs)
Certs and Tests	MIL and Marine	MIL, NEBS, and Marine	MIL and NEBS (Marine available via OEM)

Dell PowerEdge XR5610 (1U)

1 Socket / 1U Rugged Monolithic Server

- Filtered bezel for clean air operation
- Normal and Reverse airflow models
- Front or rear IO access models

Support for scalable internal storage

- Up-to 4x 2.5" NVMe, SAS, SATA SSDs
- BOSS-N.1 (2 x M.2) for OS boot
- HW NVMe RAID



Support for high-speed and memory capacity

- One 4th Generation Intel® Xeon® Scalable Server Processor with up to 32 cores, as well as Edge Enhanced Processors
- Up-to eight DDR5 4800 MT/s DIMMs

Flexible I/O

- Integrated 4x25/10GbE LOM PTP
- Up-to two risers providing OCP 3.0 and/or two PCIe Gen5x16 card slots

System Management

- iDRAC
- OpenManage Enterprise

- -5C to 55C operating temperature
- Up to 2 x SW accelerators (2 x 300W)
- Short-depth 463mm Chassis
- Industry-leading manageability and security

Technical Specifications – XR11, XR5610

Features	PowerEdge XR11	PowerEdge XR5610
CPU	One 3 rd Generation Intel® Xeon® Scalable processor with up to 36 cores supporting up to 225W processor	One Next Gen Intel® Xeon® Scalable processor, codenamed Sapphire Rapids , with up-to 32 MCC cores supporting up-to 205W processor, Edge Enhanced CPU with vRAN Boost support RTS+
Memory	Up to 8 x DDR4 RDIMMs/LRDIMMs (1TB maximum or 768GB + Optane Persistent Memory 200 Series) Optane Persistent Memory 200 Series (Barlow Pass): Yes; NVDIMM: No; DIMM Speed: Up to 3200 MT/s	Up to 8 x DDR5 DIMMs (1TB maximum) DIMM Speed: Up to 4800 MT/s
Storage (Chassis options)	Up to 4 x 2.5" SAS/SATA or NVMe SSD Internal: BOSS-S2 (2 x M.2) for boot, Internal USB	Up to 4 x 2.5" SAS/SATA SSDs or NVMe SSDs Internal: Internal BOSS-N1 (2 x M.2 NVMe) for boot
Storage Controller	HW RAID: PERC 10.5 & 11 HW NVMe RAID Chipset SATA/SW RAID: Yes	PERC 11: H755, H355, HBA355i PERC 12: H965i External: HBA355e Software RAID: S160
Network	4 x 25/10GbE LOM	4 x 25/10GbE LOM with optional SyncE support via add-in cards
PCIe slots	1 x PCIe LP Slot Gen4 (x8), up to 2 x PCIe FH Slots Gen 4 (x16/x16)	Up-to two optional risers featuring 1 x16 OCP 3.0 Gen 5 and 2 x16 FH HL PCIe Gen 5 card slots
GPU	Up to 2 x SW GPUs	Up to 2 x SW GPUs
Integrated Ports	Rear IO (Chassis Front): 1 x USB 2.0, 1 x iDRACDirect micro-USB Rear IO (Chassis Rear): 1 x USB 2.0, 1 x USB 3.0, VGA, serial Front IO (Chassis Front): 1 x USB 2.0, 1 x USB 3.0, iDRACDirect micro-USB Front IO (Chassis Rear): VGA, serial Optional Internal USB 3.0	NAF: (Normal Air Flow) (rear accessed) Chassis front ports: 1 x USB 2.0, 1 x iDRACDirect (Micro-AB USB) Chassis rear ports: 1 x USB 3.0, 1 x Mini-DisplayPort, 1 x iDRACRJ-45 dedicated port, 1 x iDRACRJ-45 Dry Input, 1 x Serial Internal ports: 1 x USB 3.0 RAF: (Reverse Air Flow) (rear accessed) Chassis front ports: 1 x USB 3.0, 1 x Mini-DisplayPort, 1 x iDRACRJ-45 dedicated port, 1 x iDRACRJ-45 Dry Input, 1 x Serial, 1 x iDRACDirect (Micro-AB USB) Internal ports: 1 x USB 3.0
System Management	iDRAC9 Enterprise, Datacenter license options; OpenManage Enterprise and Plugins (Power Manager, SupportAssist, and Update Manager). iDRACDirect	iDRAC9 Enterprise 16th generation
High Availability	Hot Plug/RAID controlled drives and PSU, Redundant Fans and BOSS-S2 (2 x M.2)	Hot Plug/RAID controlled drives, PSU, Redundant Fans and BOSS-N1 (2 x M.2)
Power Supplies	800W, 1100W -48VDC, 1400W	60mm Redundant: 800W, 1400W, 1100W , 1100W (-48VDC), 800W (-48VDC) , 1800W
Dimensions	H x W x D: 1U x 434mm x 548mm	Height: 42.8 mm (1.68 inches); Width: 482.6 mm (19 inches); Depth • Rear Accessed (NAF): With Bezel: 487.7 mm (19.2 inches); No Bezel: 463 mm (18.22 inches) • Front Accessed (RAF): With Bezel: 566.05 mm (22.28 inches); No Bezel: 472.7 mm (18.61 inches)
Form Factor	1U Short Depth (400mm class) Server	1U Short Depth (463mm Chassis) Server
Operating Environment	-5°C to 55°C	-5°C to 55°C (Restricted Configs)
Certs and Tests	MIL and NEBS	MIL-STD-810H, MIL-STD-901E and MIL-STD-461F, NEBS Level 3 (GR-63-CORE and GR-1089-CORE)

